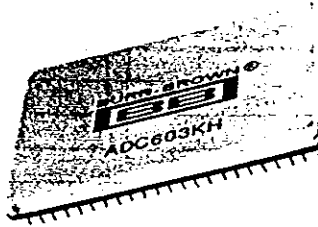

Appendix A:

MANUFACTURERS' DATA SHEETS



ADC603

12-Bit 10MHz Sampling ANALOG-TO-DIGITAL CONVERTER

FEATURES

- HIGH SPURIOUS-FREE DYNAMIC RANGE
- SAMPLE RATE: DC to 10MHz
- HIGH SIGNAL/NOISE RATIO: 68.2dB
- HIGH SINAD RATIO: 66dB
- LOW HARMONIC DISTORTION: -69.6dBc
- LOW INTERMOD. DISTORTION: -77.7dBc
- COMPLETE SUBSYSTEM: Contains Sample/Hold and Reference
- 46-PIN DIP PACKAGE
- 0°C TO $+70^{\circ}\text{C}$ AND -55°C TO $+125^{\circ}\text{C}$

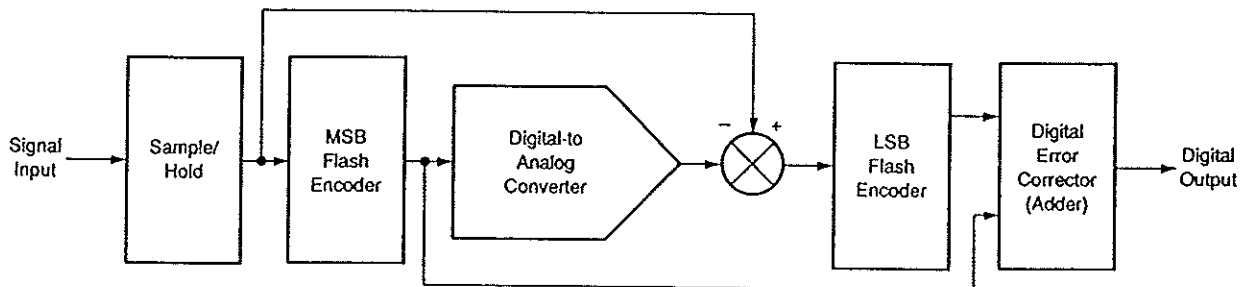
APPLICATIONS

- DIGITAL SIGNAL PROCESSING
- RADAR SIGNAL ANALYSIS
- TRANSIENT SIGNAL RECORDING
- FFT SPECTRUM ANALYSIS
- HIGH-SPEED DATA ACQUISITION
- IR IMAGING SYSTEMS
- DIGITAL RECEIVERS
- SIGINT, ECM, AND EW SYSTEMS
- DIGITAL OSCILLOSCOPES

DESCRIPTION

The ADC603 is an high performance analog-to-digital converter capable of digitizing signals at any rate from DC to 10 megasamples per second. Outstanding spurious-free dynamic range has been achieved by minimizing noise and distortion. Test summaries are furnished with each KH grade unit at no additional cost.

The ADC603 is a two-step subranging ADC subsystem containing an ADC, sample/hold amplifier, voltage reference, timing, and error-correction circuitry in a 46-pin hybrid DIP package. Logic is TTL. Two temperature ranges are available: 0°C to $+70^{\circ}\text{C}$ (JH, KH) and -55°C to $+125^{\circ}\text{C}$ (RH, SH).



International Airport Industrial Park • Mailing Address: PO Box 11400 • Tucson, AZ 85734 • Street Address: 6730 S. Tucson Blvd. • Tucson, AZ 85706
Tel: (602) 746-1111 • Twx: 910-952-1111 • Cable: BBRCORP • Telex: 066-6491 • FAX: (602) 889-1510 • Immediate Product Info: (800) 548-6132

SPECIFICATIONS

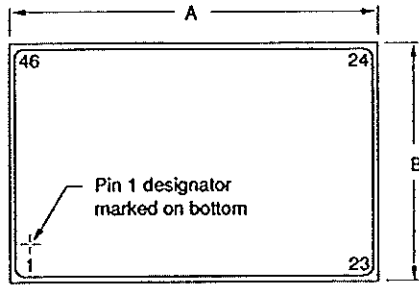
ELECTRICAL

$T_c = +25^\circ\text{C}$, 10MHz sampling rate, $R_s = 50\Omega$, $\pm V_{cc} = \pm 15\text{V}$, $+V_{DD1} = +5\text{V}$, $-V_{DD2} = -5.2\text{V}$, and 15-minute warmup in convection environment, unless otherwise noted.

PARAMETER	CONDITIONS	ADC603JH			ADC603KH			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
RESOLUTION				12			12	Bits
INPUTS								
ANALOG Input Range Input Impedance Input Capacitance	Full Scale	-1.25	1.5 5	+1.25	.	.	.	V M Ω pF
DIGITAL Logic Family Convert Command Pulse Width	Start Conversion $t =$ Conversion Period	10		TTL Compatible Positive Edge $t - 20$.	.	.	ns
TRANSFER CHARACTERISTICS								
ACCURACY Gain Error Input Offset Integral Linearity Error Differential Linearity Error No Missing Codes Power Supply Rejection	$f = 200\text{Hz}$ DC $f = 200\text{Hz}$ $f = 200\text{Hz}$: 68.3% of all Codes 99.7% of all Codes 100% of all Codes $\Delta +V_{cc} = \pm 10\%$ $\Delta -V_{cc} = \pm 10\%$ $\Delta +V_{DD1} = \pm 10\%$ $\Delta -V_{DD2} = \pm 10\%$		± 0.2 ± 0.2 0.75 0.3 0.4 0.5 Guaranteed ± 0.03 ± 0.04 ± 0.004 ± 0.01	1 0.75 1		± 0.1 . 0.5 0.25 0.3 0.4 Guaranteed	0.8 0.5 1 0.5 0.65 0.75 ± 0.07 ± 0.07 ± 0.03 ± 0.03	%FSR ⁽¹⁾ %FSR LSB LSB LSB LSB %FSR/% %FSR/% %FSR/% %FSR/%
CONVERSION CHARACTERISTICS Sample Rate Pipeline Delay	Logic Selectable	DC		10M	DC		10M	Samples/s
DYNAMIC CHARACTERISTICS								
Differential Linearity Error Spurious Free Dynamic Range Total Harmonic Distortion ⁽²⁾ (THD) Two-Tone Intermodulation Distortion ^(2,4) Signal-to-Noise and Distortion (SINAD) Ratio Signal-to-Noise Ratio (SNR) Aperture Delay Time Aperture Jitter Analog Input Bandwidth (-3dB) Overload Recovery Time	$f = 4.9\text{MHz}$: 68.3% of all Codes 99.7% of all Codes 100% of all Codes $f_s = 9.99\text{MHz}$ $f_s = 9.99\text{MHz}$ $f_s = 8.006\text{MHz}$ $f_s = 9.99\text{MHz}$ $f_s = 9.99\text{MHz}$ -20dB Input 0dB Input 2x Full-Scale Input		0.3 0.75 1 60 64 63 66 -5 9 70 40 80	1.25 -63 -61 -65 -67 35 37 100 45		. 0.5 0.6 -74 -69.6 -72.1 -77.7 66 68.5 68.2 70.1 	0.9 -66 -64 -68 -71 +9 20 140	LSB LSB LSB dB dBc ⁽³⁾ dBc dBc dB dB dB dB ns ps rms MHz MHz ns
OUTPUTS Logic Family Logic Coding Logic Levels EOC Delay Time Tri-State Enable/Disable Time Data Valid Pulse Width	Logic Selectable Logic LO, $I_{OL} = -3.2\text{mA}$ Logic HI, $I_{OH} = 160\mu\text{A}$ Data Out to DV $I_{OL} = -6.4\text{mA}$, 50% In to 50% Out		0 +2.4 5 20	+0.3 +3.5 35 45	+0.8 +5 100 60	TTL Compatible Two's Complement or Inverted Two's Complement 0 +2.4 5 20	+0.3 +3.5 35 45 +0.5 +5 100 60	V V ns ns ns
POWER SUPPLY REQUIREMENTS								
Supply Voltages: $+V_{cc}$ $-V_{cc}$ $+V_{DD1}$ $-V_{DD2}$ Supply Currents: $+I_{cc}$ $-I_{cc}$ $+I_{DD1}$ $-I_{DD2}$ Power Consumption	Operating Operating Operating		+14.25 -14.25 +4.75 -4.95 +60 -60 +280 -565 6.1	+15 -15 +5 -5.2 +60 -60 +280 -565 6.1	+15.75 -15.75 +5.25 -5.46 +60 -60 +280 -565 6.1	+14.25 -14.25 +4.75 -4.95 +60 -60 +280 -565 6.1	+15 -15 +5 -5.2 +60 -60 +330 -630 6.1	V V V V mA mA mA mA W

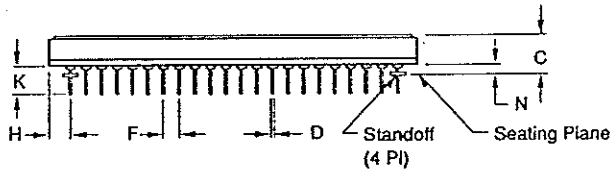
MECHANICAL

H Package — Metal and Ceramic



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	2.370	2.420	60.20	61.47
B	1.560	1.610	39.62	40.89
C	.200	.260	5.08	6.60
D	.018 Dia BASIC		0.46 Dia BASIC	
F	.100 BASIC		2.54 BASIC	
H	0.75	.115	1.91	2.92
K	.150	.190	3.81	4.83
L	1.300 BASIC		33.02 BASIC	
M	— 10°		— 10°	
N	.040	.060	1.02	1.52

NOTE: Leads in true position within 0.01" (0.25mm) R at MMC at seating plane. Pin numbers shown for reference only. Numbers may not be marked on package.



PIN ASSIGNMENTS

1	Common (Case)	46	Common (Analog)
2	NC	45	Analog Signal In
3	+V _{DO1} (+5V) Analog	44	+V _{CC} (+15V) Analog
4	S/H Out	43	-V _{CC} (-15V) Analog
5	A/D In	42	NC
6	-V _{DO2} (-5.2V) Analog	41	NC
7	NC	40	NC
8	NC	39	DNC
9	Bit 1 (MSB)	38	DNC
10	Bit 2	37	Gain Adjust
11	Bit 3	36	Offset Adjust
12	Bit 4	35	Common (Analog)
13	Bit 5	34	+V _{CC} (+15V) Analog
14	Bit 6	33	-V _{CC} (-15V) Analog
15	Bit 7	32	Common (Analog)
16	Bit 8	31	-V _{DO2} (-5.2V) Digital
17	Bit 9	30	+V _{DO1} (+5V) Analog
18	Bit 10	29	1 Pipeline Delay Select
19	Bit 11	28	0 Pipeline Delay Select
20	Bit 12 (LSB)	27	Output Logic Invert
21	+V _{DO1} (+5V) Digital	26	Common (Digital)
22	Data Valid Output	25	Tri-State $\overline{\text{ENABLE}}$
23	Common (Digital)	24	Convert Command In

ORDERING INFORMATION

	ADC603	()	H
Basic Model Number	_____		
Performance Grade Code	_____		
J, K:	0°C to +70°C Case Temperature		
R, S:	-55°C to +125°C Case Temperature		
Package Code	_____		
H: Metal and Ceramic			

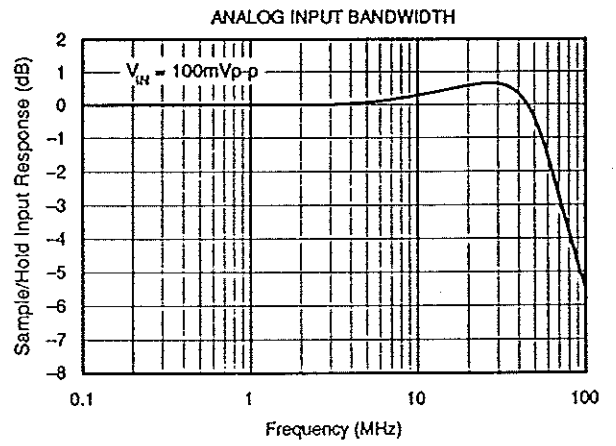
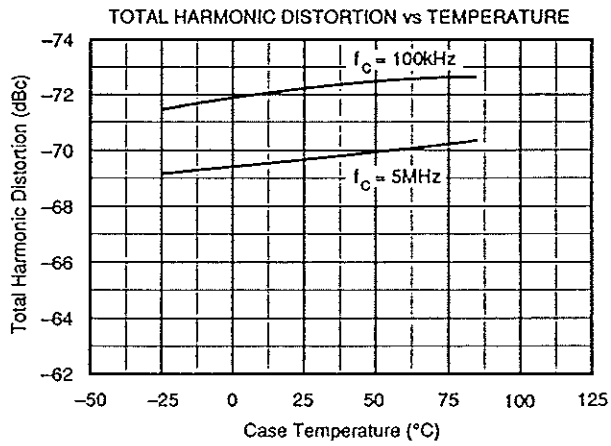
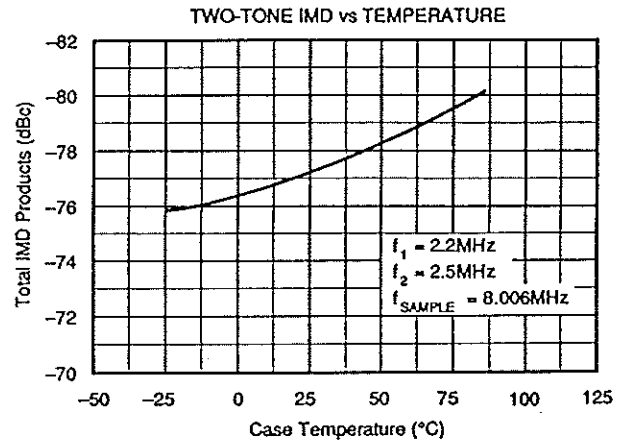
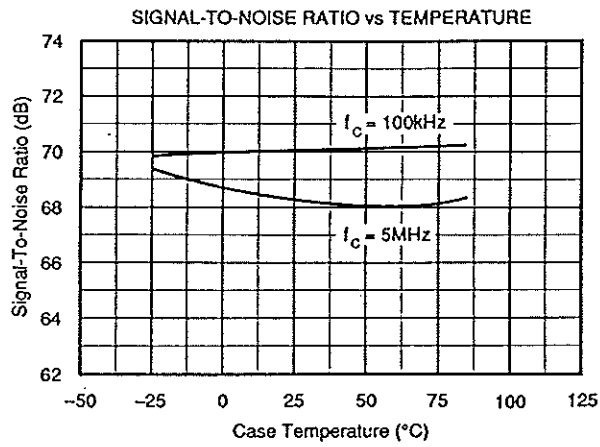
ABSOLUTE MAXIMUM RATINGS

±V _{CC}	±16.5V
+V _{DO1}	+7V
±V _{DO2}	-7V
Analog Input	±5V
Logic Input	-0.5V to +V _{DO1}
Case Temperature	+125°C
Junction Temperature	+165°C
Storage Temperature	-65°C to +165°C

Stresses above these ratings may permanently damage the device.

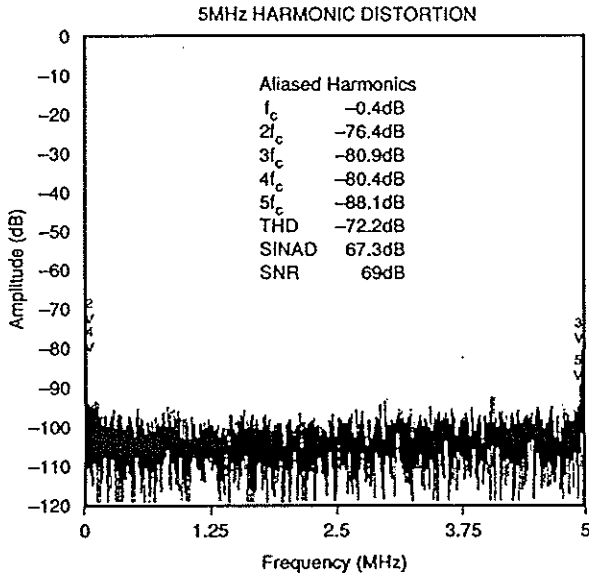
TYPICAL PERFORMANCE CURVES

$\pm V_{CC} = \pm 15V$, $+V_{DD1} = +5V$, $-V_{DD2} = -5.2V$, $R_3 = 50\Omega$, 15-minute warmup, and $T_c = +25^\circ C$, unless otherwise noted. All plots are 4096 point FFTs.

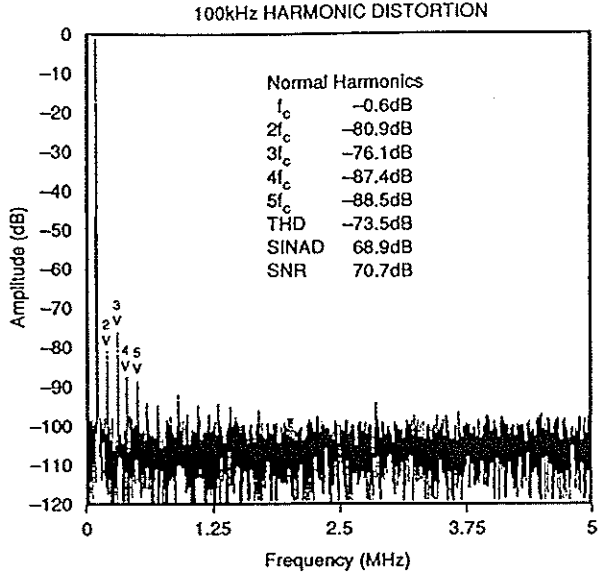


TYPICAL PERFORMANCE CURVES

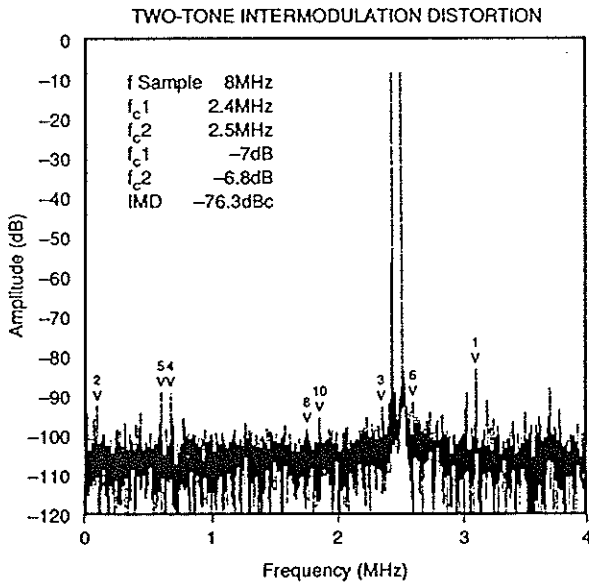
$\pm V_{cc} = \pm 15V$, $+V_{DD1} = +5V$, $-V_{DD2} = -5.2V$, $R_s = 50\Omega$, 10MHz sample rate, 15-minute warmup, and $T_c = +25^\circ C$, unless otherwise noted. All plots are 4096-point FFTs.



NOTE: Sample rate = 9.99 MHz; even harmonics folded to left edge and odd harmonics folded to right edge. Any non-harmonically related spurious products show clearly in the center.



NOTE: Sample rate = 9.99 MHz; harmonics appear in normal order.



NOTE: Sample rate = 8MHz; highest IMD product is cursor number 1: $f_1 + f_2$. The second-order -76.3dBc product determines the wideband spurious-free dynamic range of this example. For RF applications third-order IMD products such as those at cursors 3 and 6 are the limiting spurs. Under these conditions spurious-free dynamic range is limited by $2f_2 + f_1$ to 84.3dBc.

Sample rates of 10MHz show similar results.

TWO-TONE INTERMODULATION DISTORTION PRODUCTS

CURSOR	IMD	FREQUENCY	dB
1	2nd order : $f_1 + f_2$	3.086395621579MHz	-83.1
2	2nd order : $f_2 - f_1$	0.080140734949MHz	-91.4
3	3rd order : $2f_1 - f_2$	2.339718530102MHz	-92.4
4	3rd order : $2f_1 + f_2$	0.666536356529MHz	-88.4
5	3rd order : $2f_2 - f_1$	0.586395621579MHz	-88.2
6	3rd order : $2f_2 + f_1$	2.580140734949MHz	-91.1
7	4th order : $3f_1 - f_2$	3.246677091478MHz	-109
8	4th order : $3f_1 + f_2$	1.753322908522MHz	-100
9	4th order : $2f_2 - 2f_1$	0.130281469898MHz	-114.8
10	4th order : $2f_2 + 2f_1$	1.833463643471MHz	-95
11	4th order : $3f_2 - f_1$	2.926114151681MHz	-115.4
12	4th order : $3f_2 + f_1$	1.913604378421MHz	-98.2

NOTE: IMD products in this table are referred to full-scale (0dB). To refer IMD to carrier, subtract the larger of f_{c1} or f_{c2} . In this example, IMD referred to carrier will be 6.8dB higher (worse) than the full-scale value shown.

THEORY OF OPERATION

The ADC603 is a two-step subranging analog-to-digital converter. This architecture is shown in Figure 1. The major system building blocks are: sample/hold amplifier, MSB flash encoder, DAC and error amplifier, LSB flash encoder, digital error corrector, and timing circuits. The ADC603 uses hybrid technology with laser-trimmed integrated circuits mounted in a multilayer ceramic package to integrate this complex circuit into a complete analog-to-digital converter subsystem with state-of-the-art performance.

Conceptually, the subranging technique is simple: sample and hold the input signal, convert to digital with a coarse ADC, convert back to analog with a coarse-resolution (but high-accuracy) DAC, subtract this voltage from the S/H output, amplify this "remainder," convert to digital with a second coarse ADC, and combine the digital output from the first ADC (MSB) with the digital output from the second ADC (LSB). In practice, however, achieving high conversion speed without sacrificing accuracy is a difficult task.

The analog input signal is sampled by a high-speed sample/hold amplifier with low distortion, fast acquisition time and very low aperture uncertainty (jitter). A diode bridge sampling switch is used to achieve an acceptable compromise between speed and accuracy. The diode bridge switching transients are buffered from the analog input by a high input impedance buffer amplifier. Since the hold capacitor does not appear in the feedback of the diode bridge output buffer,

the capacitor can acquire the signal in 25ns. The low-bias-current output buffer is then required to settle to only the resolution (7 bits) of the first (MSB) flash encoder in 25ns, while an additional 60ns is allowed for settling to the resolution (12 bits) of the second (LSB) flash encoder. Sample/hold droop appears as only an offset error and does not effect linearity.

Both the MSB and the LSB flash encoder (ADC) function are performed by multiplexing one high-speed 7-bit resolution converter formed by parallel-connecting two 6-bit flash ADCs. The DAC voltage reference is also used to generate reference voltages for the MSB and LSB encoder to compensate drift errors. Buffering and scaling amplifiers are laser-trimmed to minimize voltage offset errors and optimize gain (input full-scale range) symmetry.

The subtraction DAC is an ECL 7-bit resolution monolithic DAC with 14-bit accuracy. Laser-trimmed thin-film nichrome resistors and high-speed bipolar circuitry allow the DAC output to settle to 14-bit accuracy in only 35ns.

A "remainder" or coarse conversion-error voltage is generated by resistively subtracting the DAC output from the output of the sample/hold amplifier. Before the second (LSB) conversion, the "remainder" is amplified by a wideband fast-settling two-input amplifier with a gain of 32V/V. To prevent overload on large amplitude transients, the active input is switched off to blank the amplifier input from the beginning of the S/H acquisition time to the end of the MSB encoder update time.

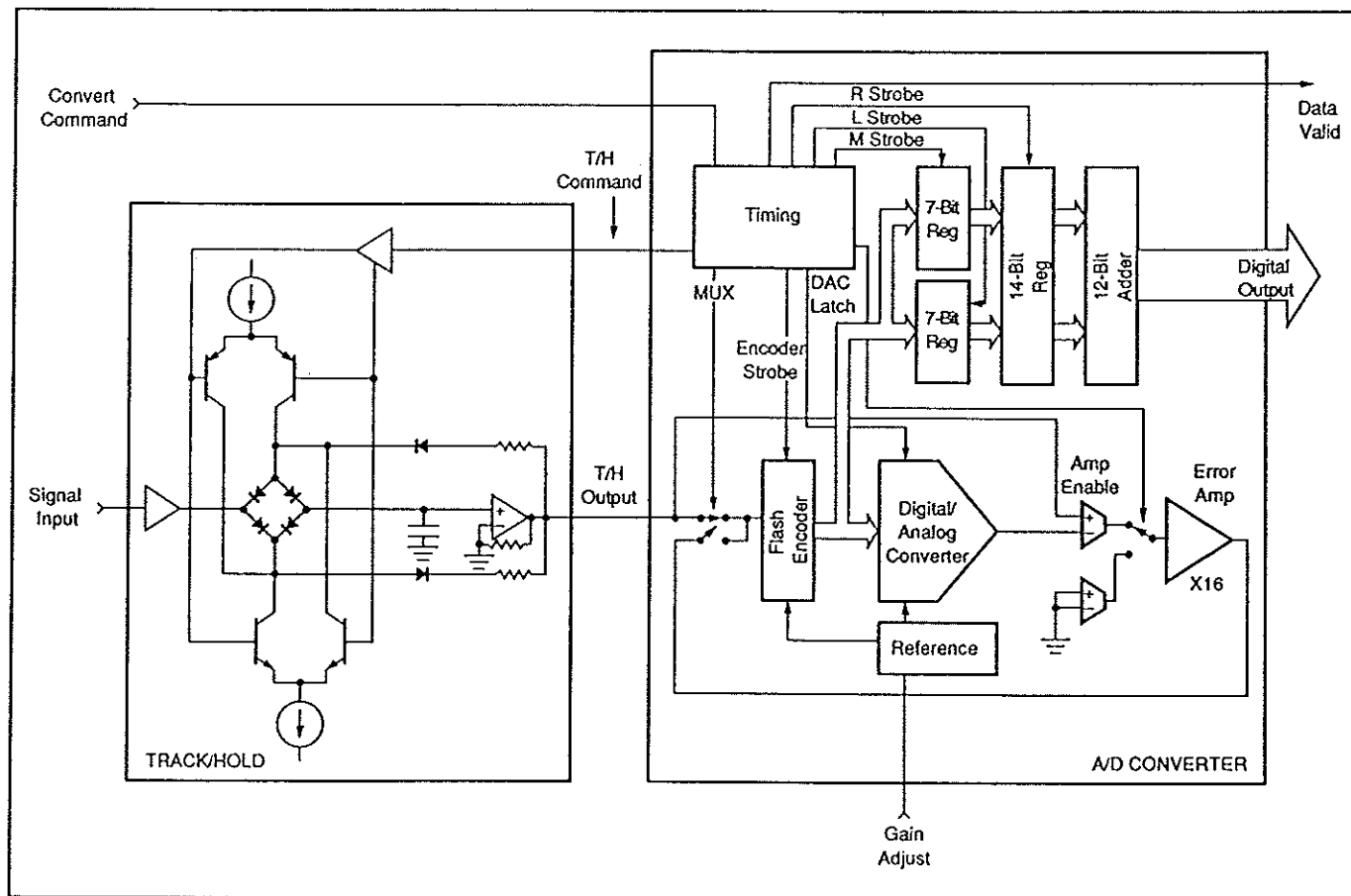


FIGURE 1. ADC603 Block Diagram—A Two-Step Subranging Architecture.

Internal timing circuits (ECL logic is used internally) supply all the critical timing signals necessary for proper operation of the ADC603. Some noncritical timing signals are also generated in the digital error correction circuitry. Timing signals are laser-trimmed for both pulse width and delay. ECL logic is used for its speed, low noise characteristics and timing delay stability over a wide range of temperatures and power supply voltages. Basic timing is derived from the output of a three-stage shift register driven by a synchronized 20MHz oscillator.

The convert command pulse is differentiated to allow triggering by pulses from as narrow as 10ns to as wide as 80% duty cycle.

The ADC603 timing technique generates a variable width S/H gate pulse which is determined by the conversion command pulse period minus a fixed 67ns ADC conversion time. ADC603 conversion rates are therefore possible somewhat above the 10MHz specification, but S/H acquisition time is sacrificed and accuracy is rapidly degraded. Converters with guaranteed operation at 10.24MHz sample rate are available on special order.

The output of the MSB and LSB encoders are read into separate 7-bit latches. The latched MSB data, along with the latched LSB data, is then read into a 14-bit latch after the leading edge of the LSB strobe and before being applied to the adder, where the actual error correction takes place. These latches eliminate any critical timing problems that could result when the converter is operated at the maximum conversion rate.

The function of the digital error correction circuitry is to assemble the 7-bit words from the two flash encoders into a 12-bit output word. A data valid (DV) pulse is also generated which is used to indicate when output data can be latched into an external register. This DV pulse is delayed 6ns after the output data has settled to allow sufficient set-up time for an external TTL data latch. A high-speed latch such as a 74F174 is recommended.

The 14-bit register output is then sent to a 12-bit adder where the final data output word is created. The MSB data forms the

most significant seven bits of a 12-bit word, with the last five bits being assigned zeros. In a similar fashion, the LSB data from the least significant bits forms the other input to the adder, with the first five bits being assigned zeros. As two 12-bit words are being added, the output of the adder could exceed 12 bits in range; however, the final data output is only a 12-bit word, so a means of detecting an overrange is included to prevent reading erroneous data. The converter data output is forced to all ones for a full-scale input or overrange. The data output does not "roll-over" if the converter input exceeds its specified full-scale range of $\pm 1.25V$.

DISCUSSION OF PERFORMANCE

DYNAMIC PERFORMANCE TESTING

The ADC603 is a very high performance converter and careful attention to test techniques is necessary to achieve accurate results. Spectral analysis by application of a fast Fourier transform (FFT) to the ADC digital output will provide data on all important dynamic performance parameters: total harmonic distortion (THD), signal-to-noise ratio (SNR) or the more severe signal-to-noise-and-distortion ratio (SINAD), and intermodulation distortion (IMD).

A typical test setup for performing high-speed FFT testing of analog-to-digital converters is shown in Figure 2. Highly accurate phase-locked signal sources allow high resolution FFT measurements to be made without using window functions. By choosing appropriate signal frequencies and sample rates, an integral number of signal frequency periods can be sampled. As no spectral leakage results, a "rectangular" window (no window function) can be used. This was used to generate the typical FFT performance curves shown on page 5.

If generators cannot be phase-locked and set to extreme accuracy, a very low side-lobe window must be applied to the digital data before executing an FFT. A commonly used window such as the Hanning window is not appropriate for testing high performance converters; a minimum four-sample Blackman-Harris window is strongly recommended.⁽¹⁾ To

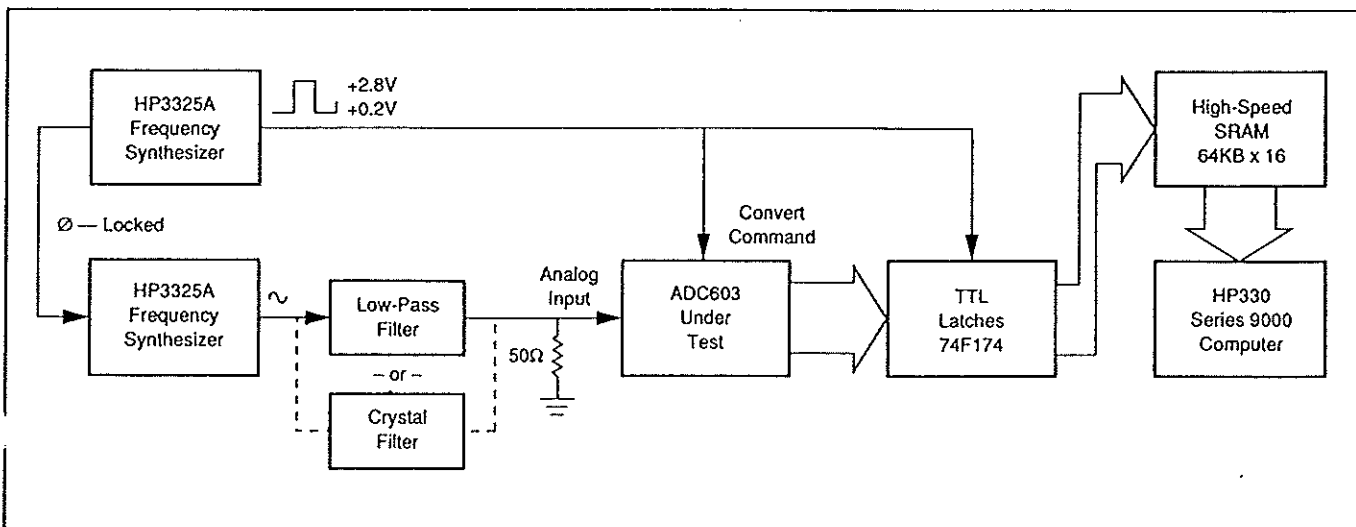
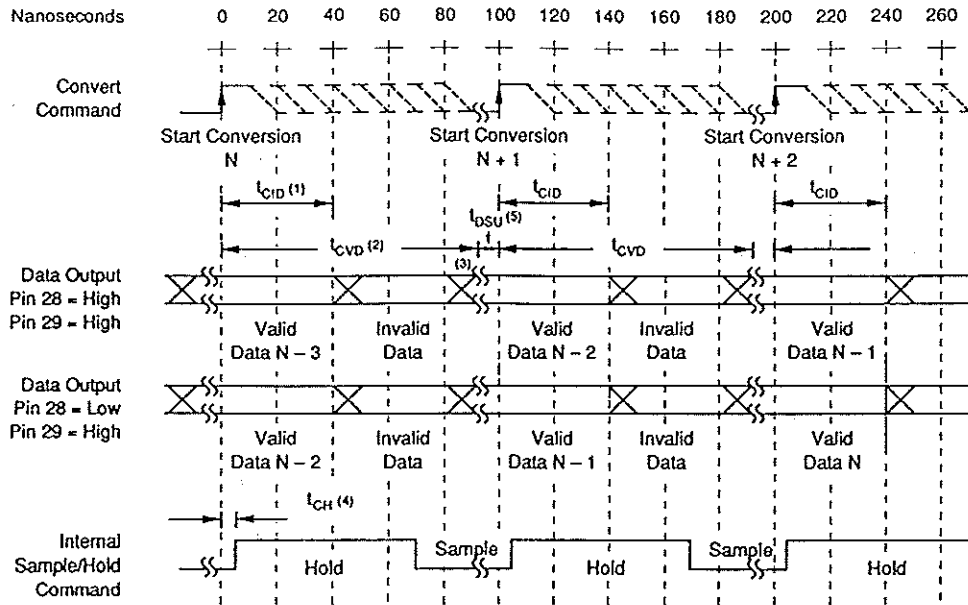


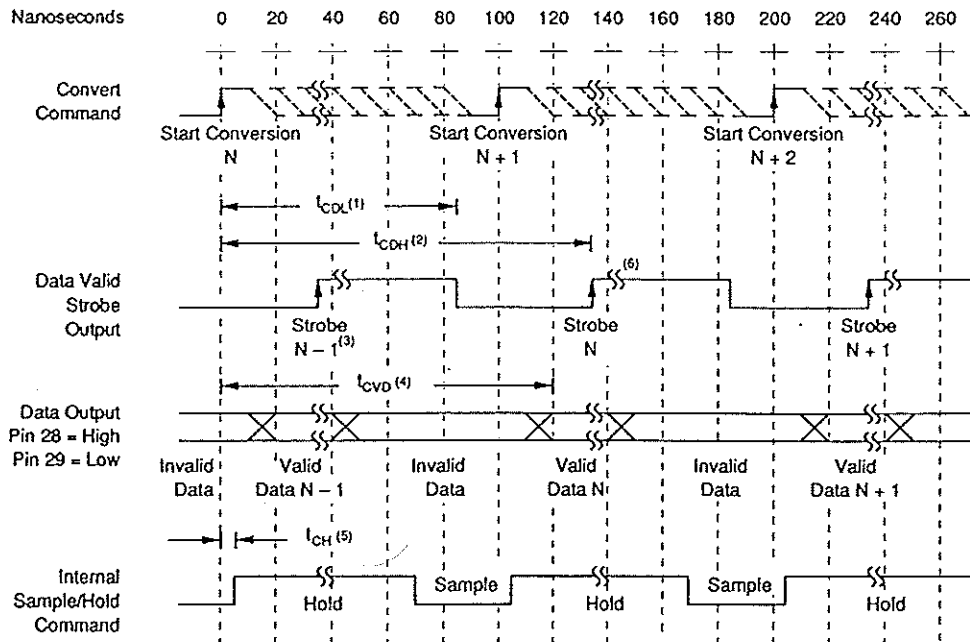
FIGURE 2. Block Diagram of FFT Test for THD, SNR, and SINAD.



NOTES: (1) t_{cd} = Delay time from Convert Command to Invalid Data. Typical value = 40ns. Independent of conversion rate. (2) t_{cvd} = Delay time from Convert Command to Valid Data. Typical value = 93ns. Independent of conversion rate. (3) The \llcorner symbol indicates the portion of the waveform that will "stretch out" at lower conversion rates. (4) t_{ch} = Delay time from Convert Command to the internal hold. Typical value = 6ns. Independent of conversion rate. (5) t_{osu} = data setup time. This depends on conversion rate and may be calculated by:

$$t_{osu} = \frac{1}{f_{SAMPLE}} - t_{cvd}$$

FIGURE 13. Convert Command Strobe Timing.

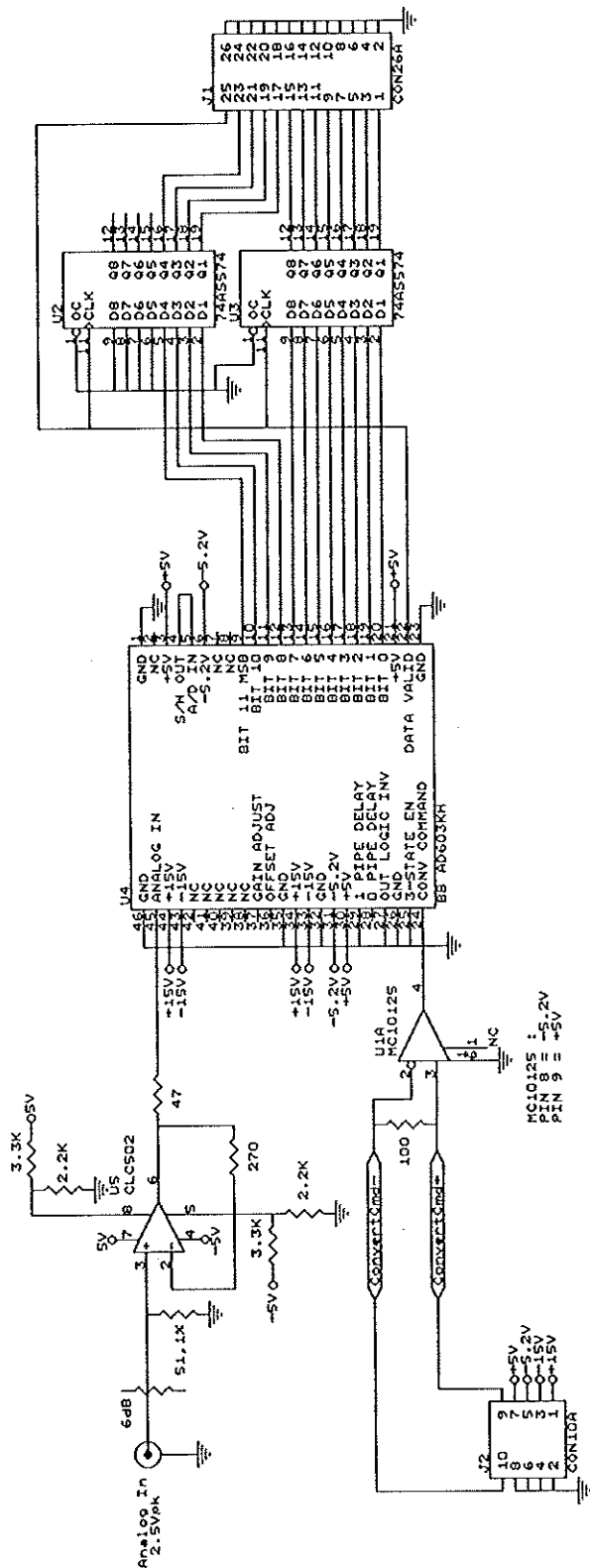


NOTES: (1) t_{col} = Delay time from Convert Command to the falling edge of Data Valid Strobe. Typical value = 85ns. Independent of conversion rate. (2) t_{cdh} = Delay time from Convert Command to the rising edge of Data Valid Strobe. Typical value = 135ns. Independent of conversion rate. (3) If Conversion "N" is the first conversion, then there is no Strobe N-1, and the Data Valid Strobe Signal will simply be high until t_{col} after the first Convert Command. (4) t_{cvd} = delay time from Convert Command to Valid Data. Typical value = 120ns. Independent of conversion rate. (5) t_{ch} = Delay time from Convert Command to Internal Hold Command. Typical value = 6ns. Independent of conversion rate. (6) The \llcorner symbol indicates the portion of the waveform that will "stretch out" at lower conversion rates.

FIGURE 14. Data Valid Strobe Timing.

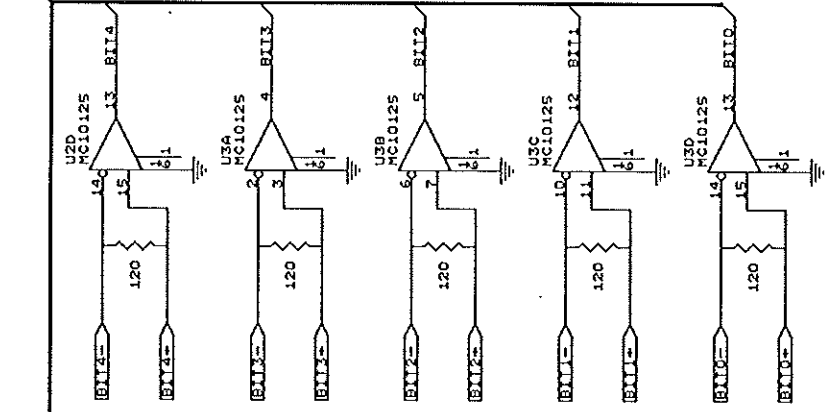
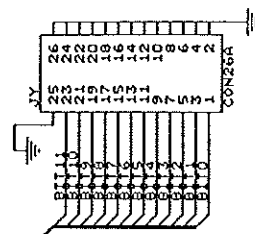
Appendix B:

Schematics

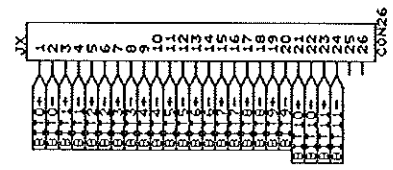
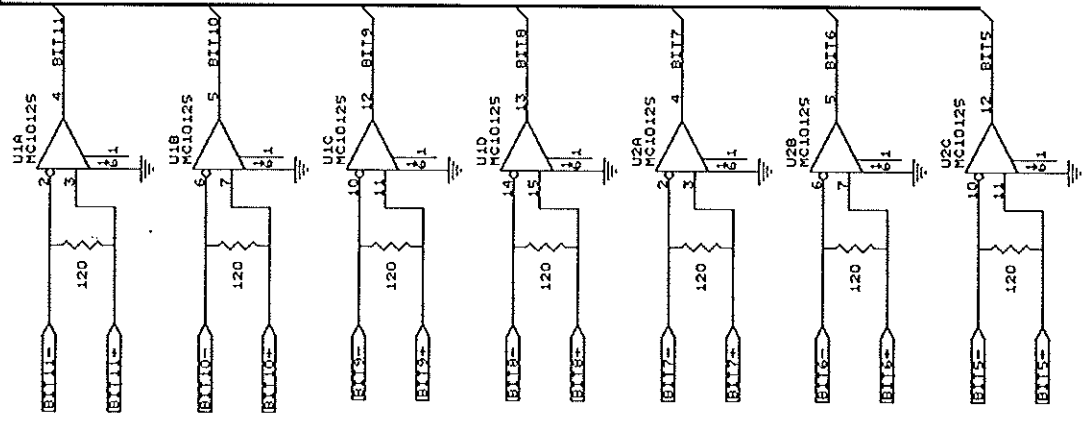


2.2uF & .01uF capacitors on all power pins.

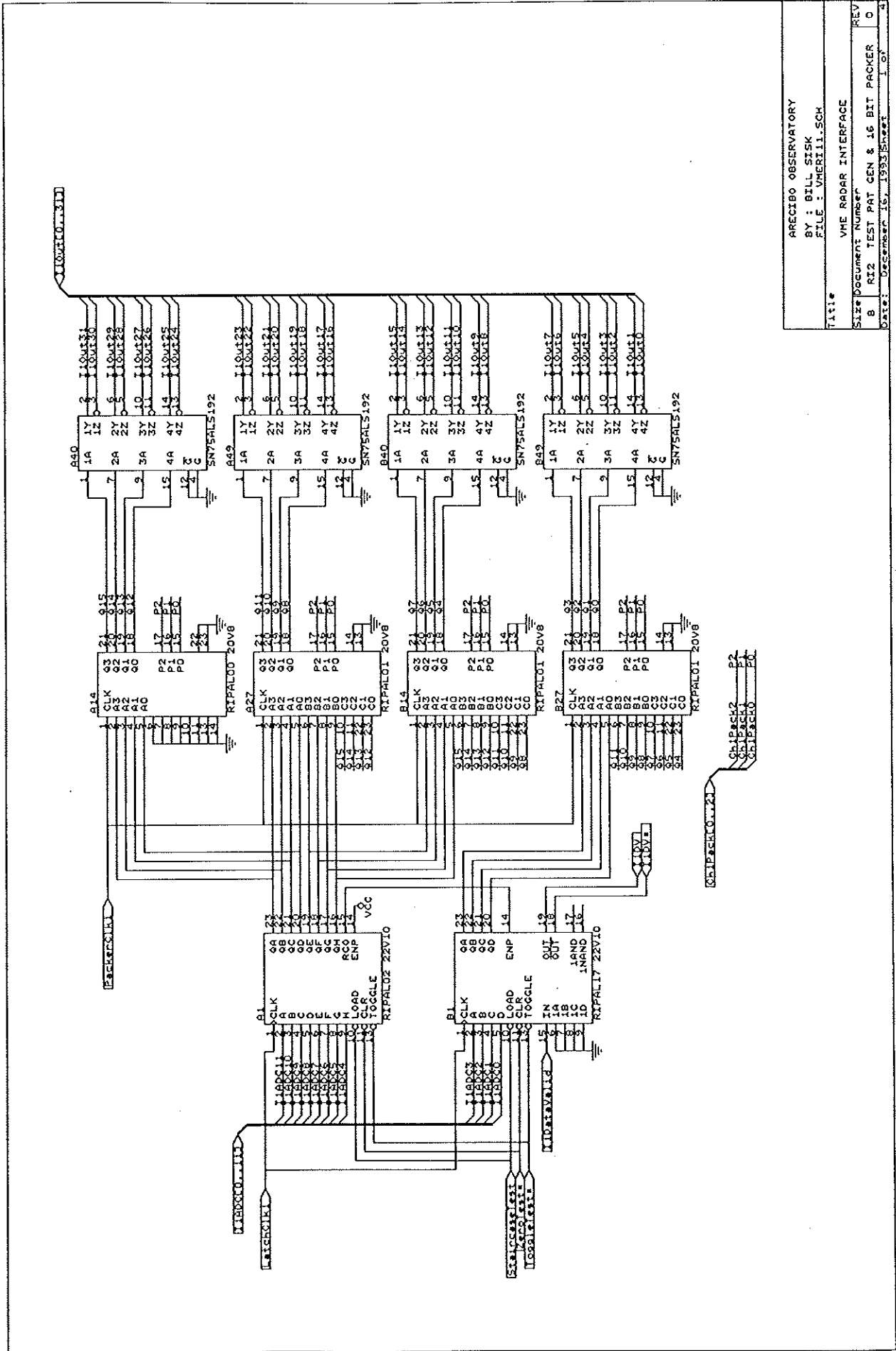
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TITLE	
VME RADAR INTERFACE	
Size	Document Number
B	R11 A-T-O CONVERTER
Date:	December 16, 1993 Sheet 1 of 2



MC10125 : PIN 9 = +5.0V
 MC10125 : PIN 8 = -5.2V



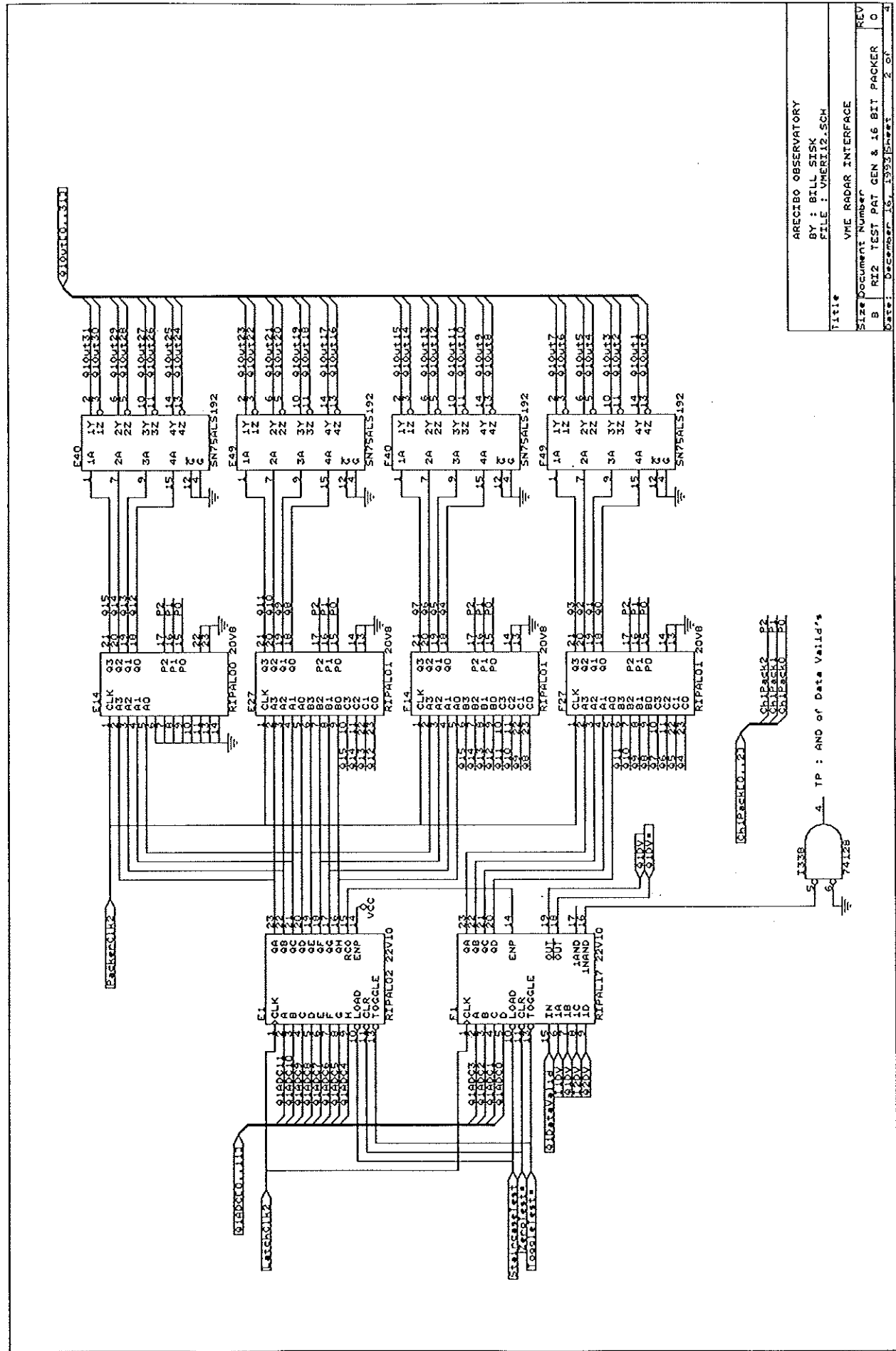
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REV	0
Date:	December 17, 1993 Sheet 2 of 2



ARECIBO OBSERVATORY
 BY : BILL SISK
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Title
 VME RADAR INTERFACE

SIZE Document Number
 B R12 TEST PAT GEN & 16 BIT PACKER REV
 Date: December 15, 1993 Sheet 1 of 4

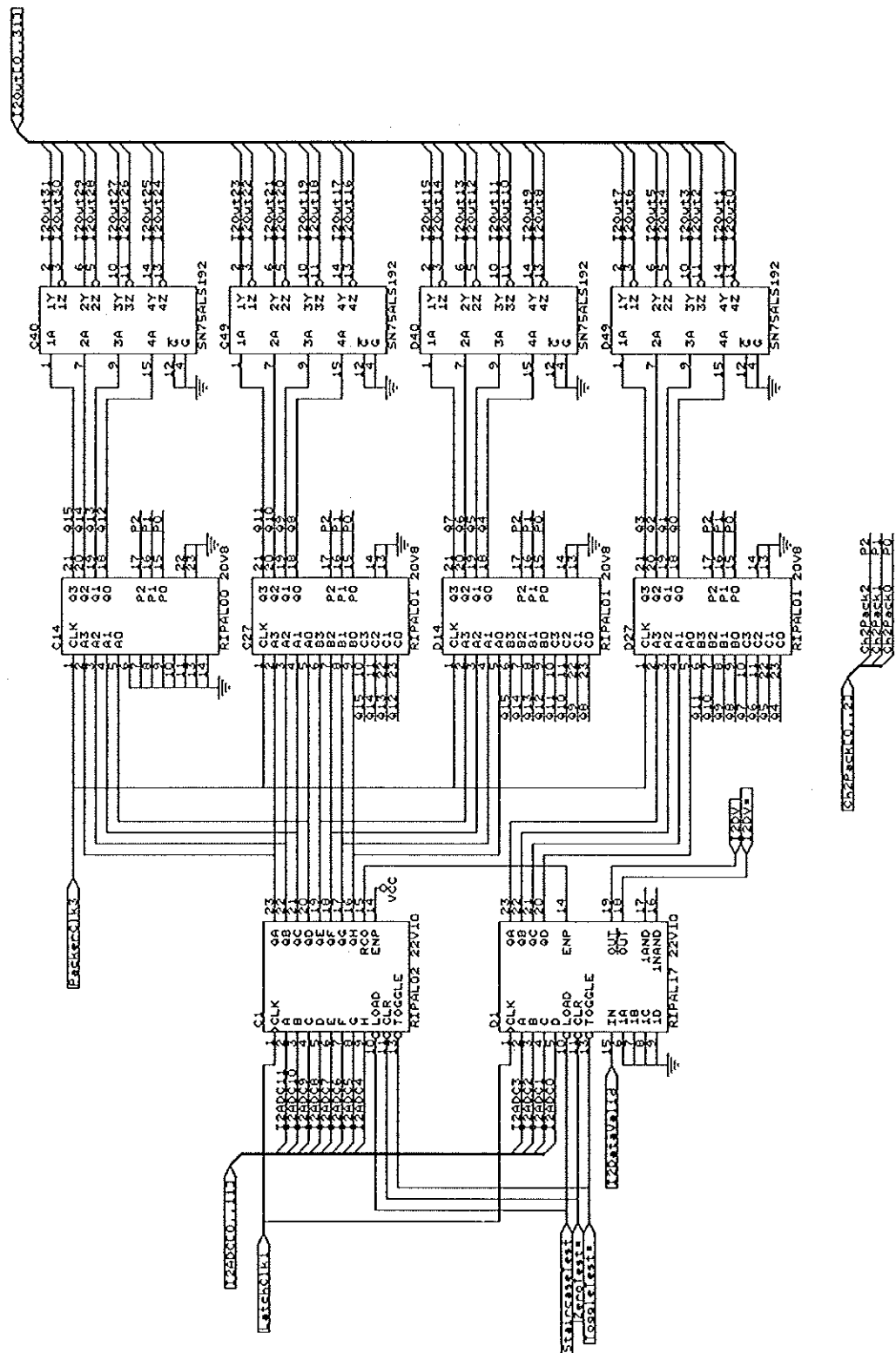


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 VME RADAR INTERFACE

Size Document Number
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Date: December 16, 1993 Sheet 2 of 2



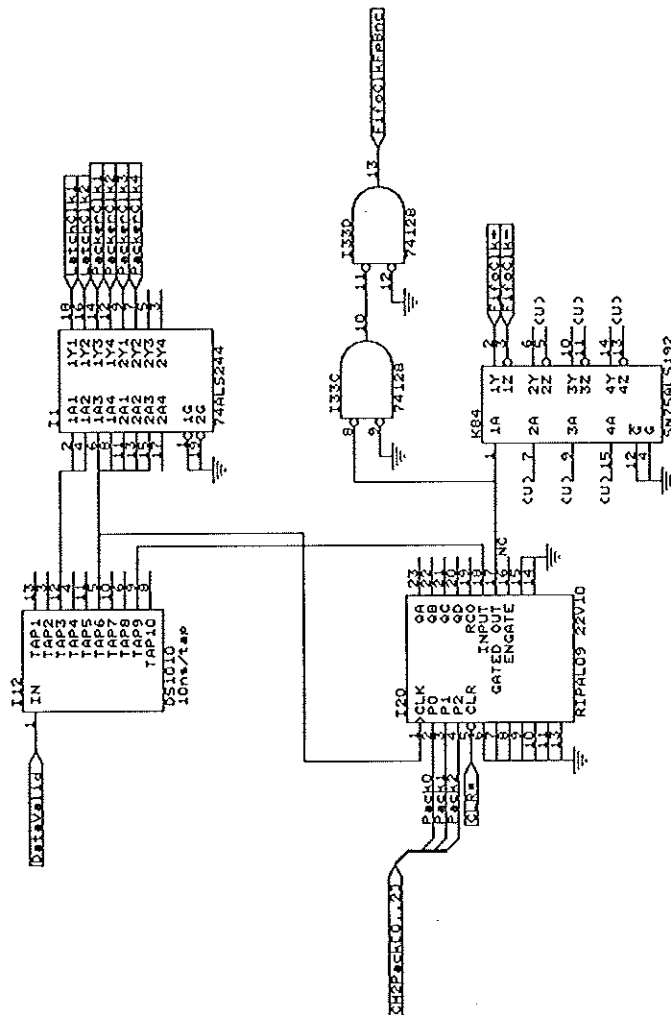
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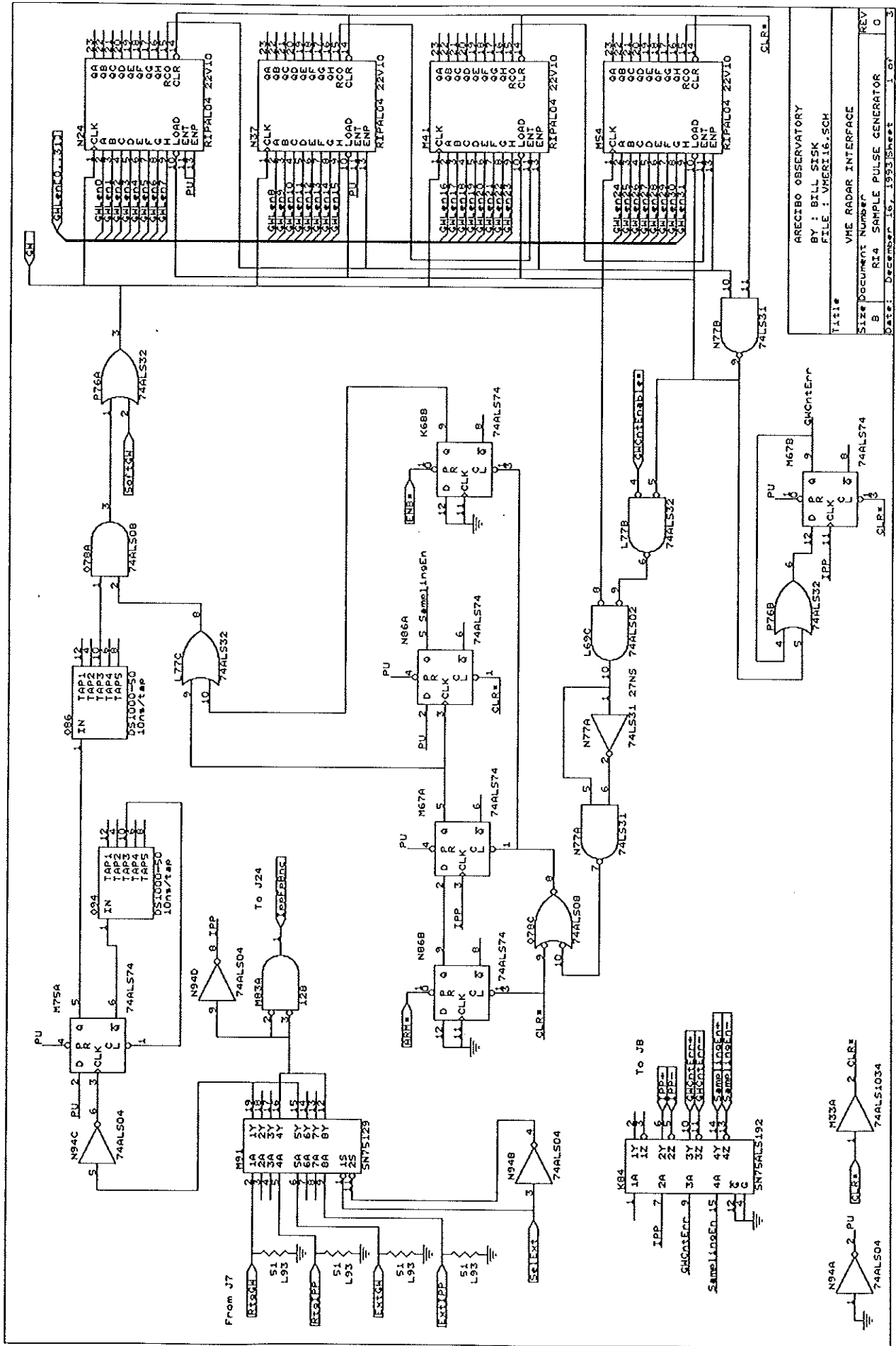
Date: December 16, 1993 Sheet 3 of 4

RIPAL00.23
 C40PASK2 P2
 C40PASK1 P1
 C40PASK0 P0



FORMAT DECODER TABLE

COUNTER PRESET	DCBA	CYCLE LENGTH	LOGIC EQTN'S
0	0000	1	A = P2 + P1 + P0
1	0001	4	B = P1 + P0
3	0011	9	C = P1 + P0
15	1111	16	D = P2

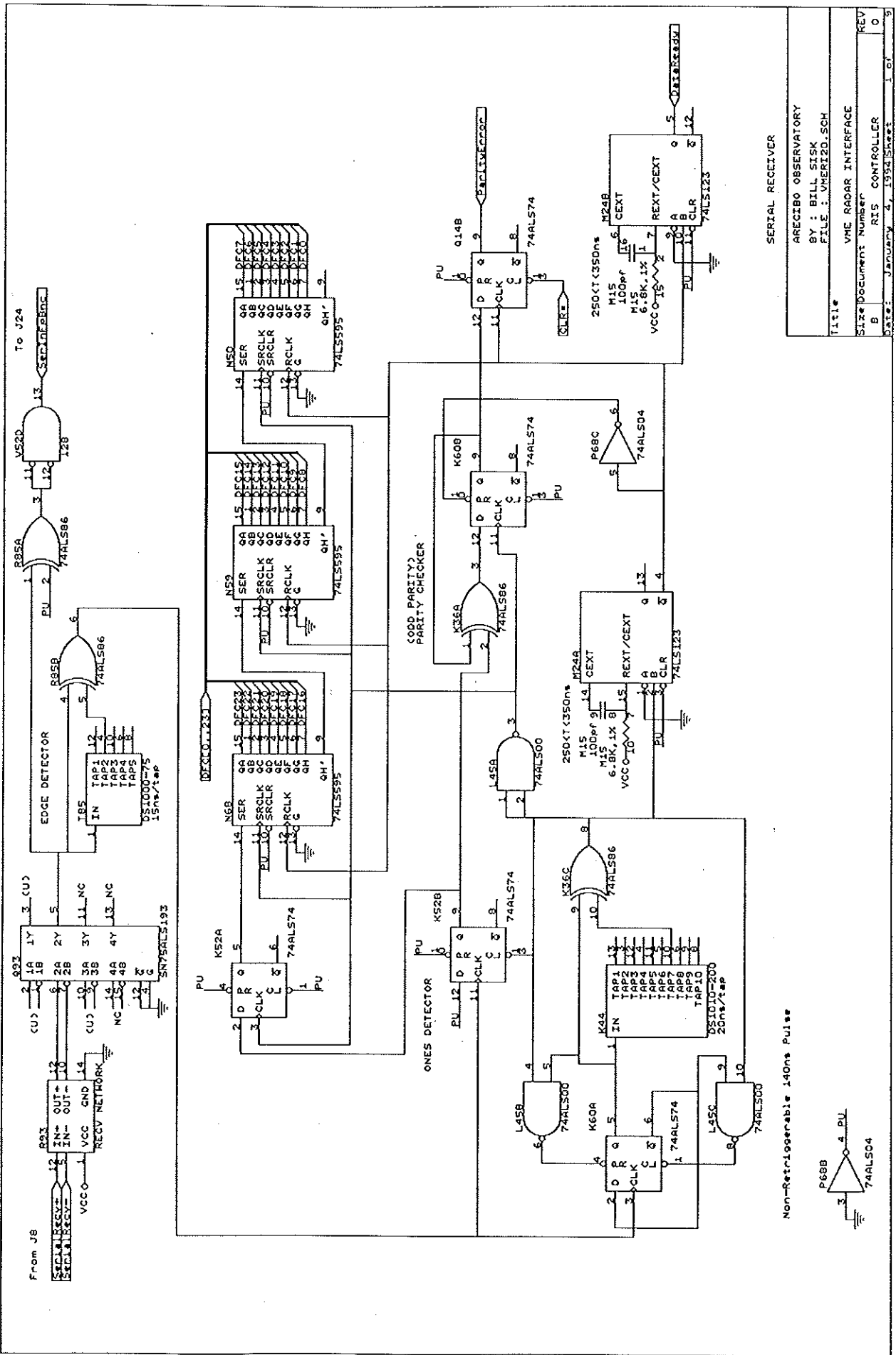


Title
 Size
 B
 Date: December 15, 1993 Sheet 1 of 3

ARECIBO OBSERVATORY
 BY : BILL SISK
 FILE : VMEI16.SCH

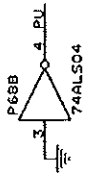
VME RADAR INTERFACE
 Size
 B
 Date: December 15, 1993 Sheet 1 of 3

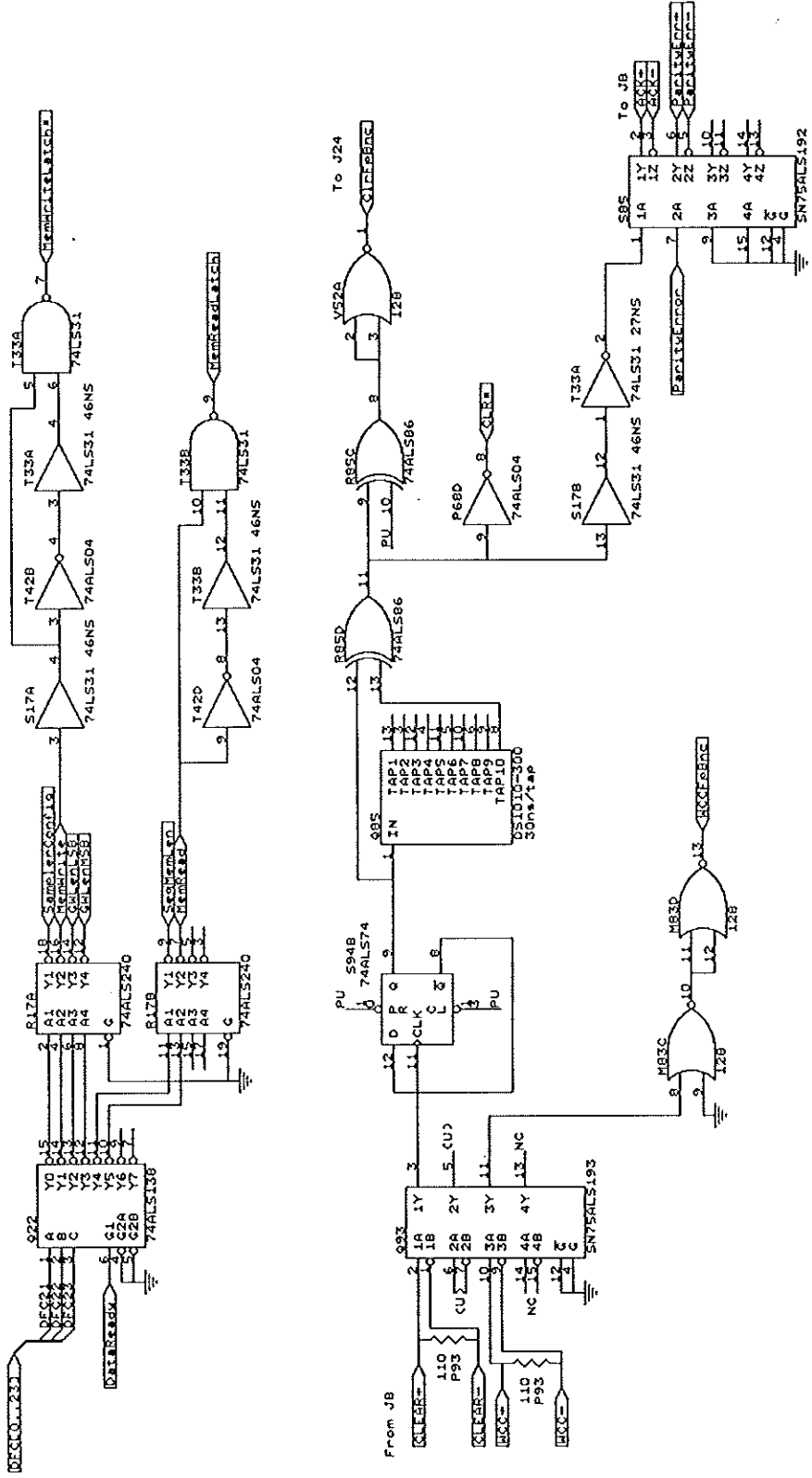
Title
 Size
 B
 Date: December 15, 1993 Sheet 1 of 3



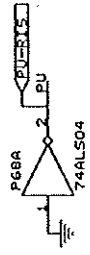
SERIAL RECEIVER
 ARECIBO OBSERVATORY
 BY : BILL SISK
 FILE : VMER120.SCH
 Title
 Schematic Number
 B RIS CONTROLLER
 0
 Date: JANUARY 4, 1984 Sheet 1 of 5

Non-Retriggerable 140ns Pulse





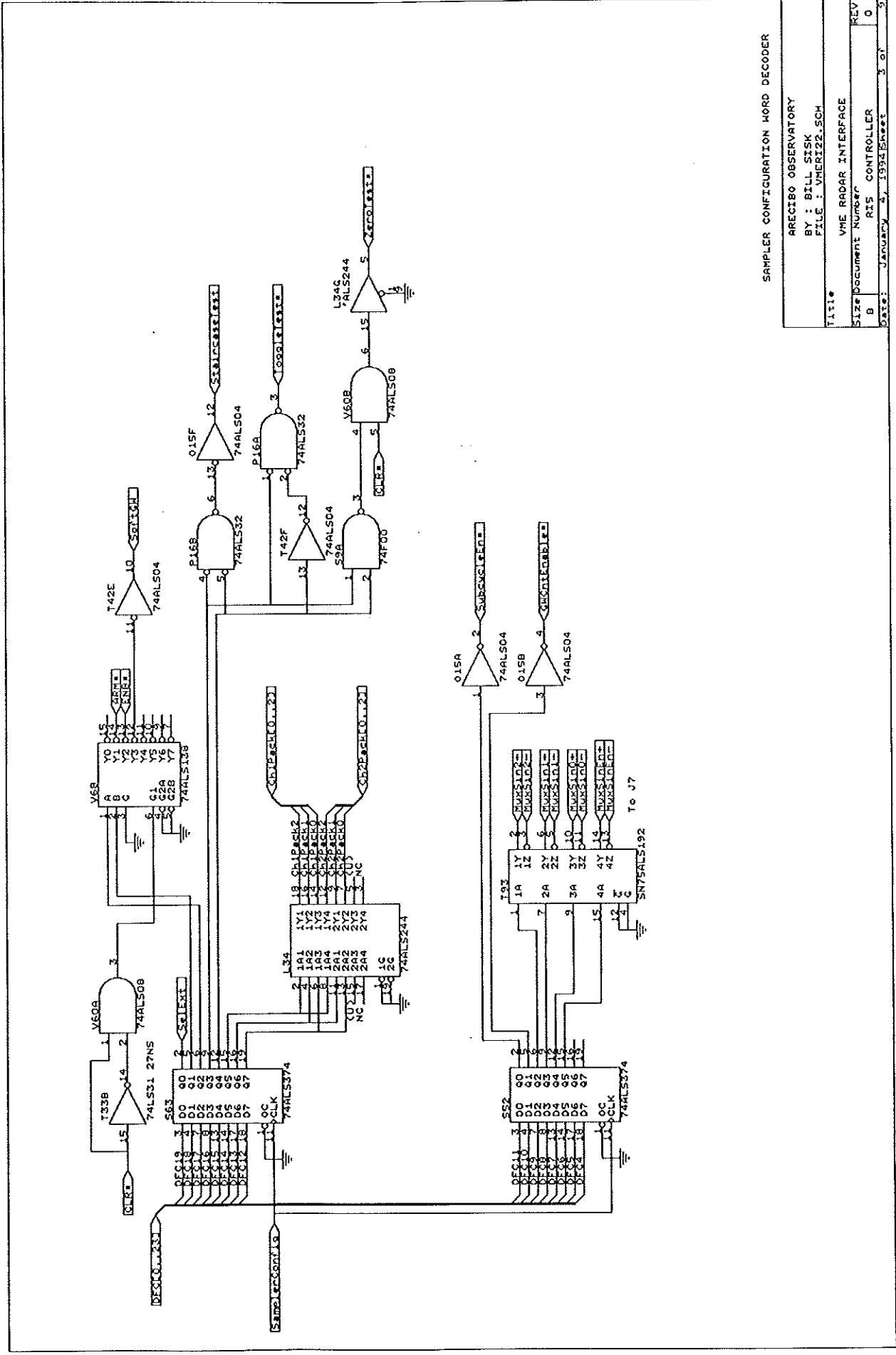
COMMAND BITS DECODER
 ARECIBO OBSERVATORY
 BY : BILL STICK
 FILE : VMER121.SCH



Title
 UME RADAR INTERFACE
 Size Document Number
 B R15 CONTROLLER
 Date: January 5, 1994 Sheet 2 of 3

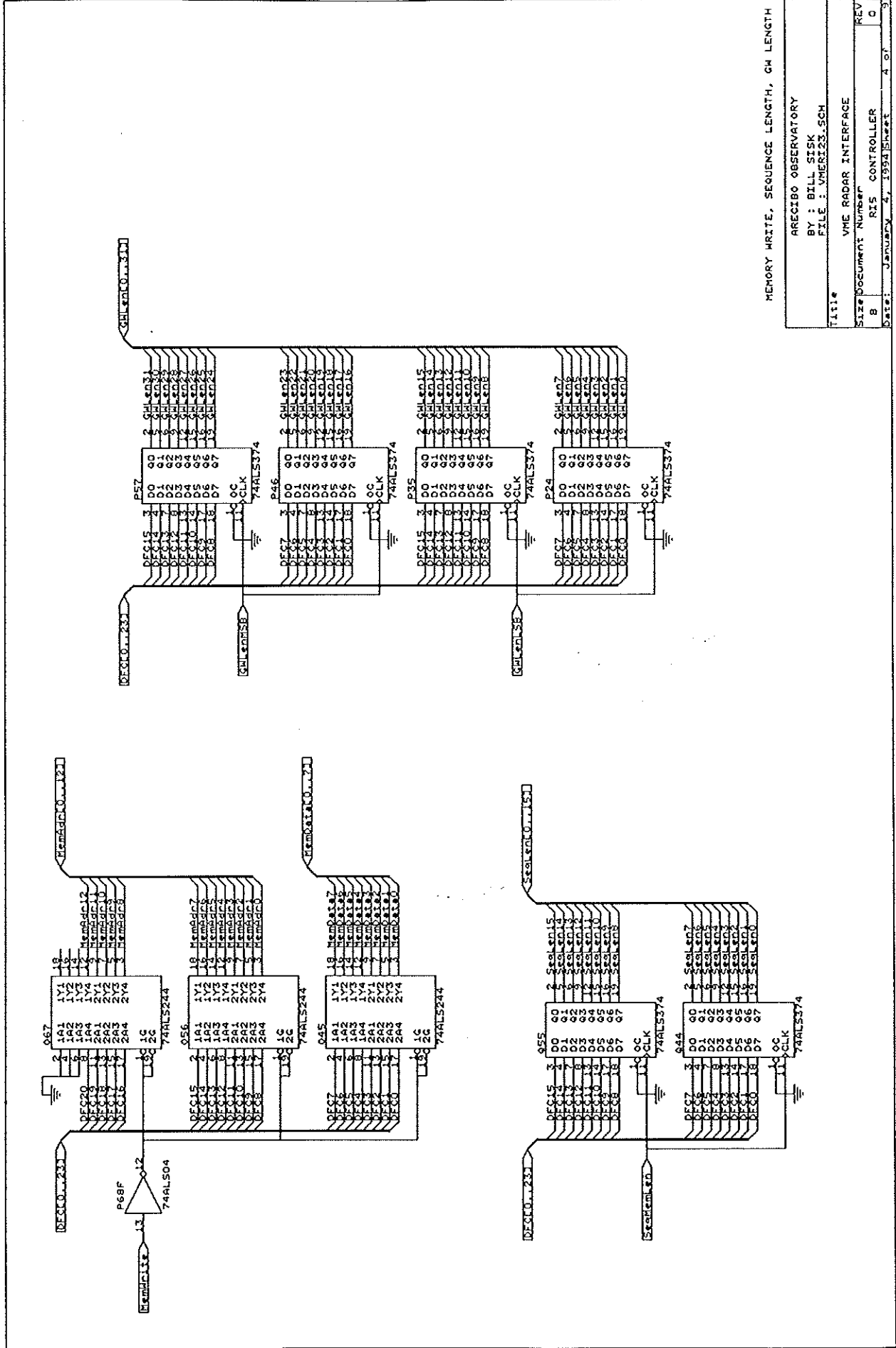
(U) : Gate is being used in another location.

REV	0
REV	0
REV	0



SAMPLER CONFIGURATION WORD DECODER

ARECIBO OBSERVATORY	
BY : BILL SISK	
FILE : VMERI22.SCH	
TATI*	
VME RADAR INTERFACE	
SIZE	Document Number
B	R/S CONTROLLER
Date:	January 4, 1993 Sheet 3 of 3



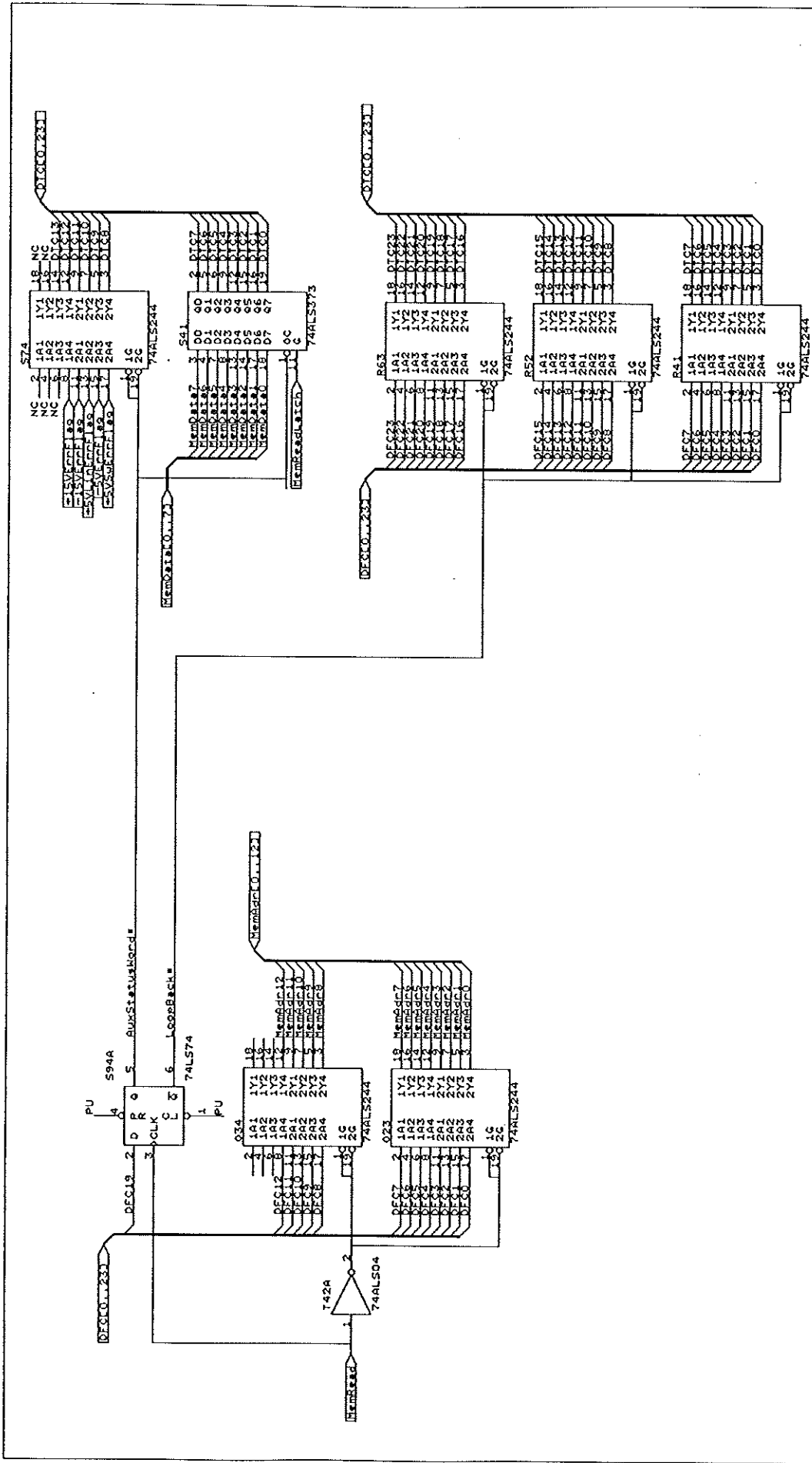
MEMORY WRITE, SEQUENCE LENGTH, CM LENGTH

ARECIBO OBSERVATORY
 BY : BILL SISK
 FILE : UMERIS3.SCH

TITLE
 VME RADAR INTERFACE

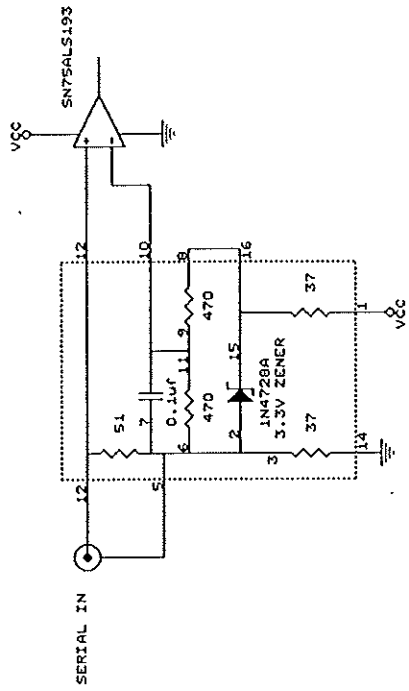
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Date: JANUARY 4, 1993 15:43 4 of 9

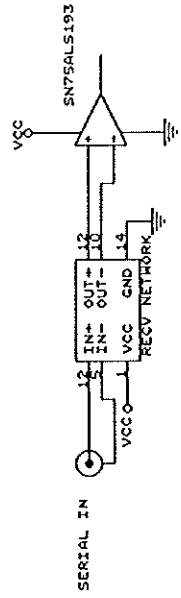


AUXILIARY STATUS WORD / LOOPBACK

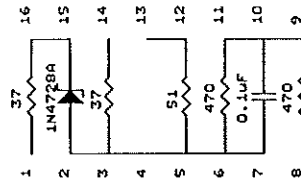
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BY : BILL SISK	
FILE : VMER24.SCH	
Title	
VME RADAR INTERFACE	
Size	Document Number
B	RIS CONTROLLER
REV	0
Date:	January 4, 1983 Sheet 5 of 9



B. DETAILED SCHEMATIC



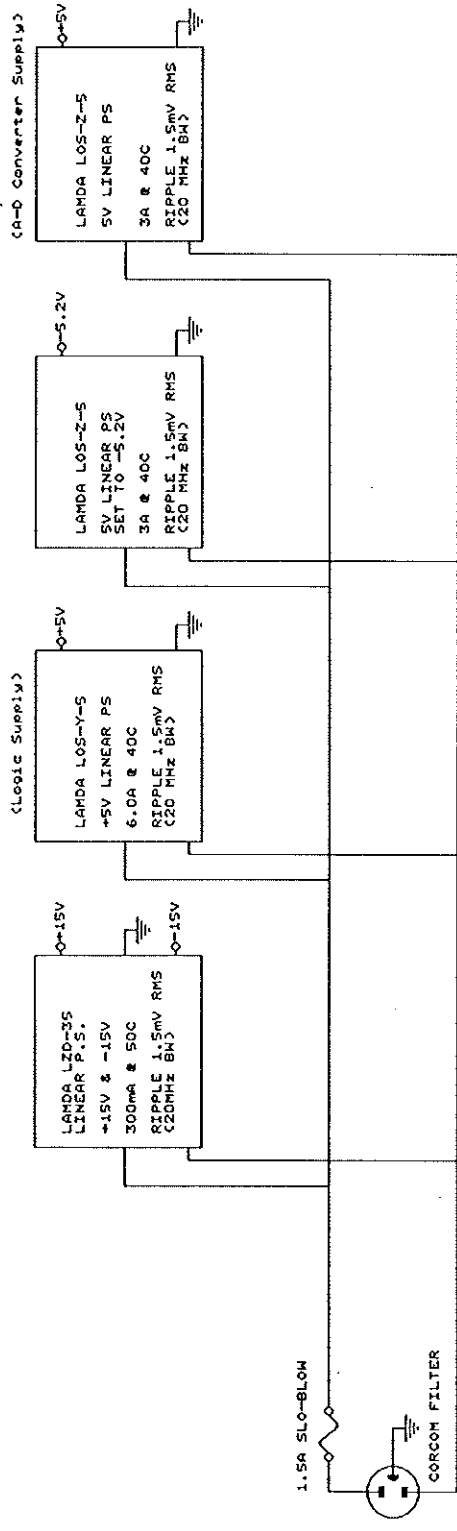
A. SCHEMATIC USAGE



C. DIP CARRIER DETAIL

ARECIBO OBSERVATORY
 BY : BILL SISK
 FILE : VMER127.SCH

Title		VME RADAR INTERFACE
Size	Document Number	8
REV	RIS CONTROLLER	0
Date	January 4, 1992	Sheet 8 of 9

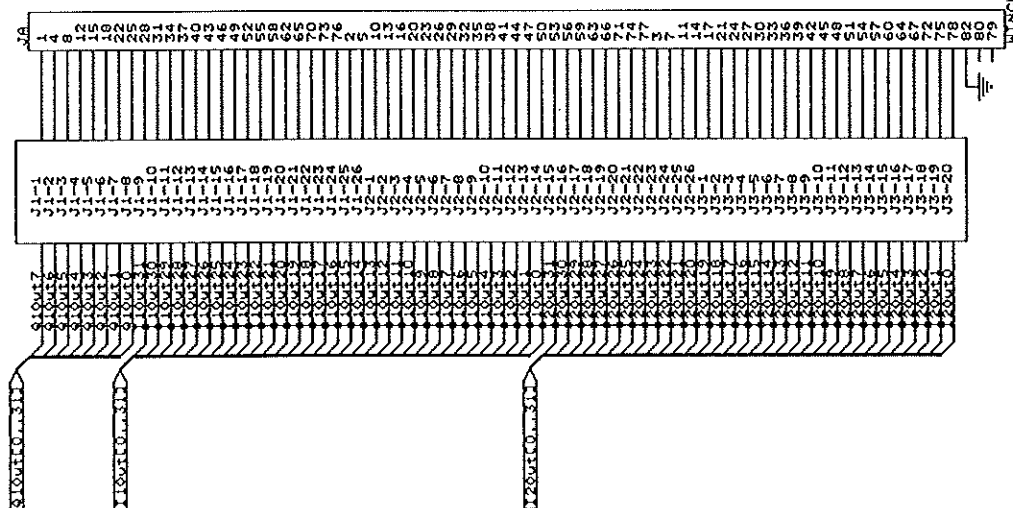
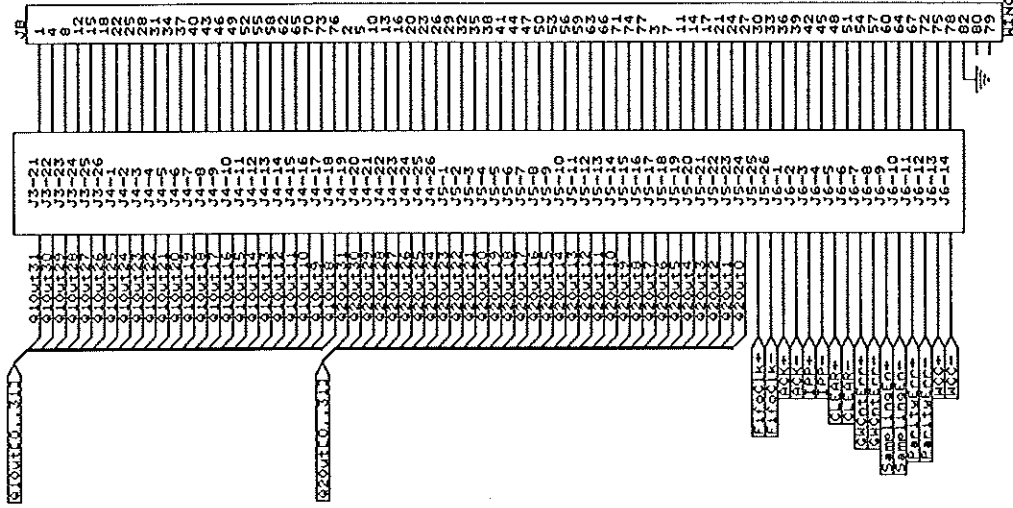
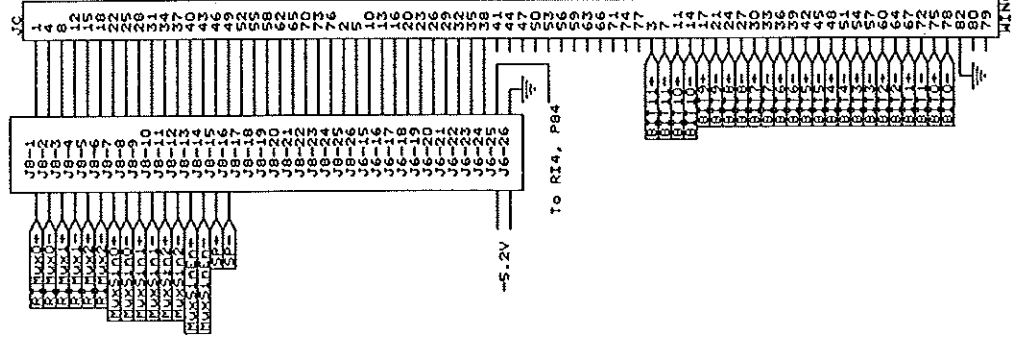


ARECIBO OBSERVATORY
 BY : BILL STICK
 FILE : VMER30.SCH

Title
 VME RADAR INTERFACE

SIZE Document Number
 B R16 POWER SUPPLY

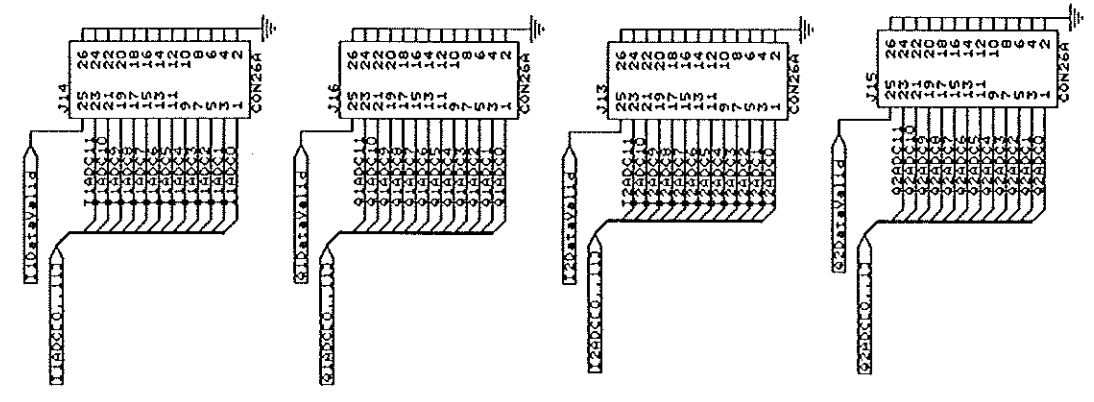
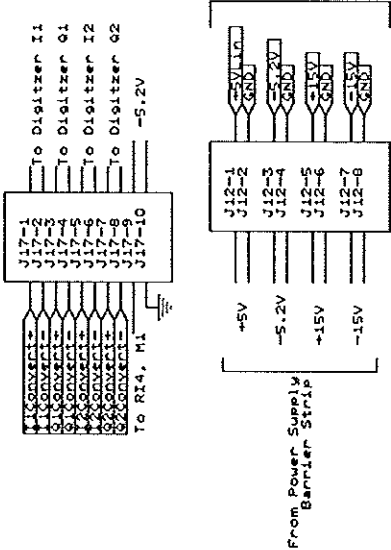
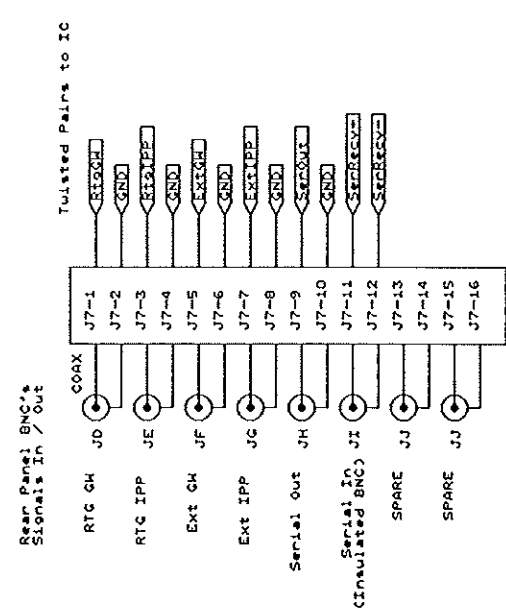
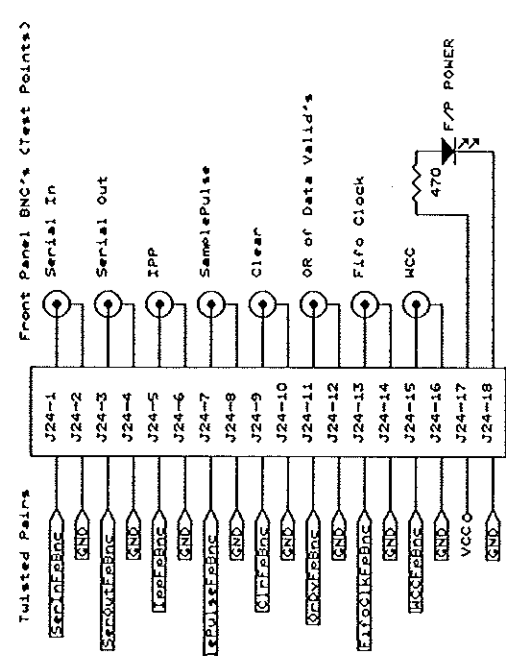
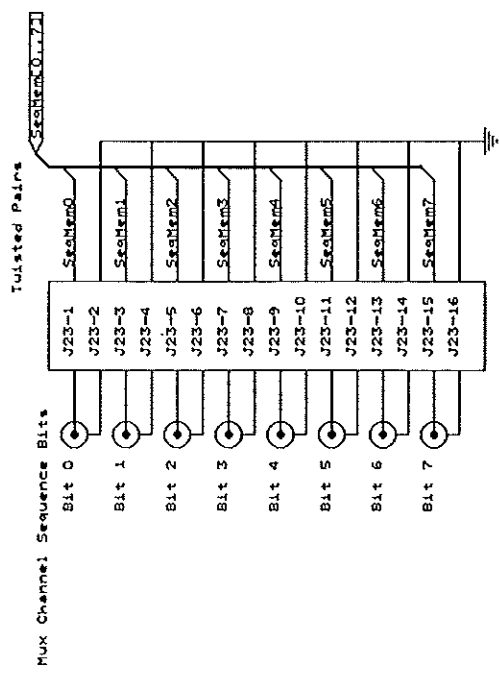
Date: January 4, 1994 Sheet 1 of 1



ARECIBO OBSERVATORY
 BY : BILL SISK
 FILE : VMERIS1.SCH
 TITLE : VME RADAR INTERFACE
 Size Document Number
 B R17 CONNECTOR WIRING
 Date: January 13, 1993 Sheet 1 of 2

HINCH CON-75P

HINCH CON-75P

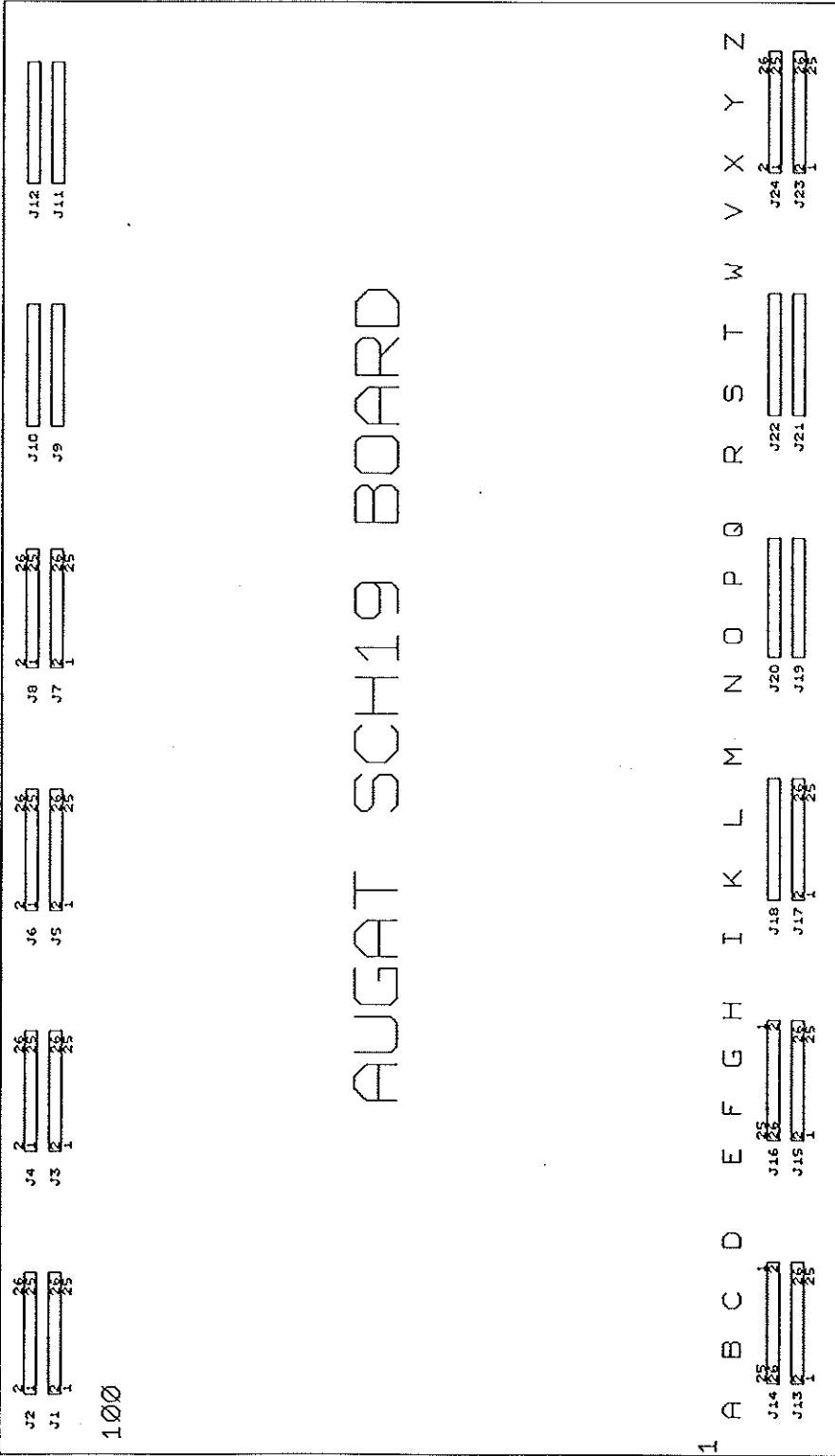


ARECIBO OBSERVATORY
BY: BILL SISK
FILE: VME832.SCH

Title
VME RADAR INTERFACE
Size Document Number
B
R17 CONNECTOR WIRING
REV
D
Date: January 4, 1983 Sheet 2 of 2

To RIS, pg.7

REAR



FRONT

ARECIBO OBSERVATORY
 BY : BILL SISK
 FILE : VMER133.SCH

Title

VME RADAR INTERFACE

Size Document Number

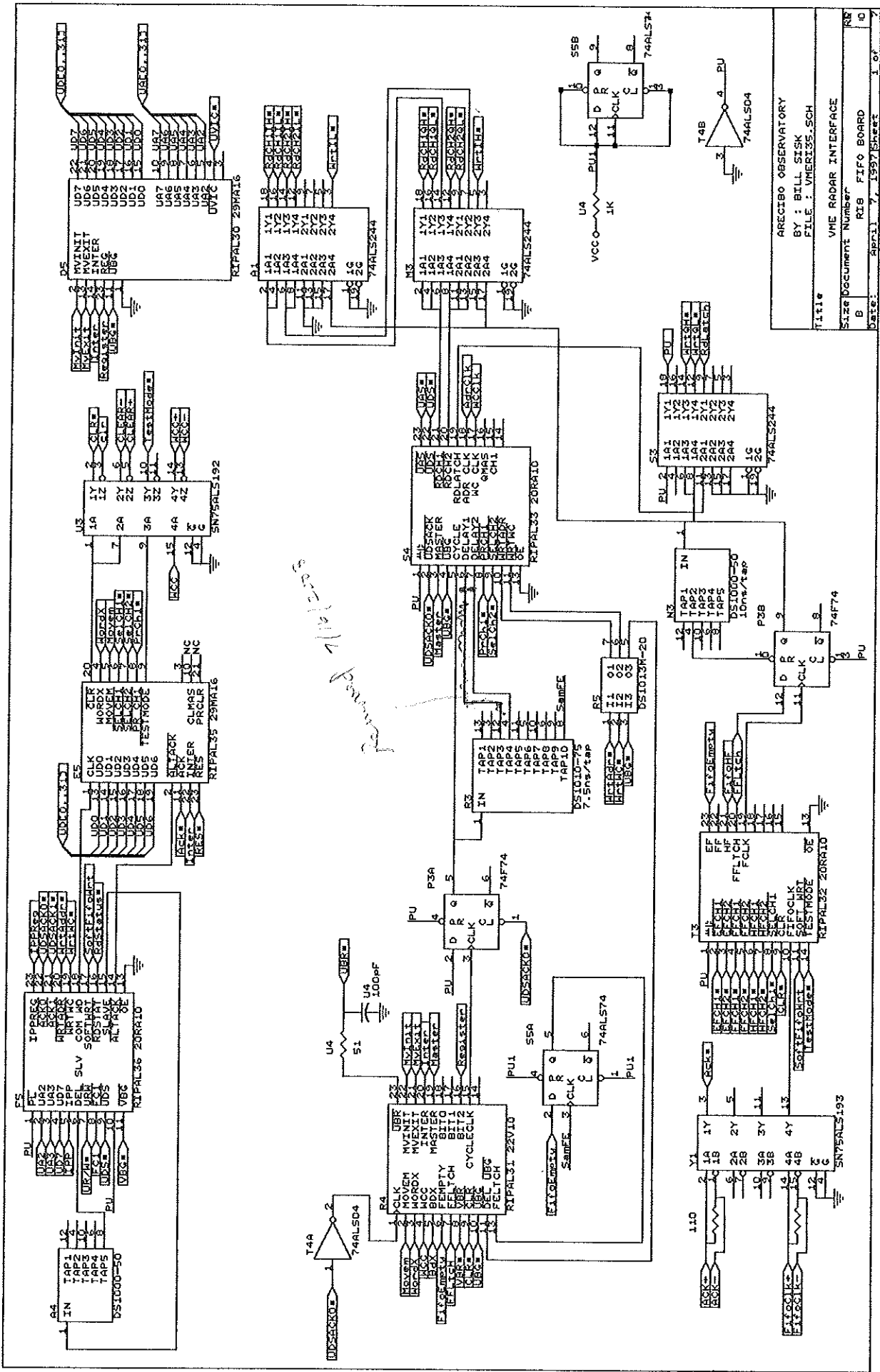
B AUGAT SCH19 BOARD LAYOUT

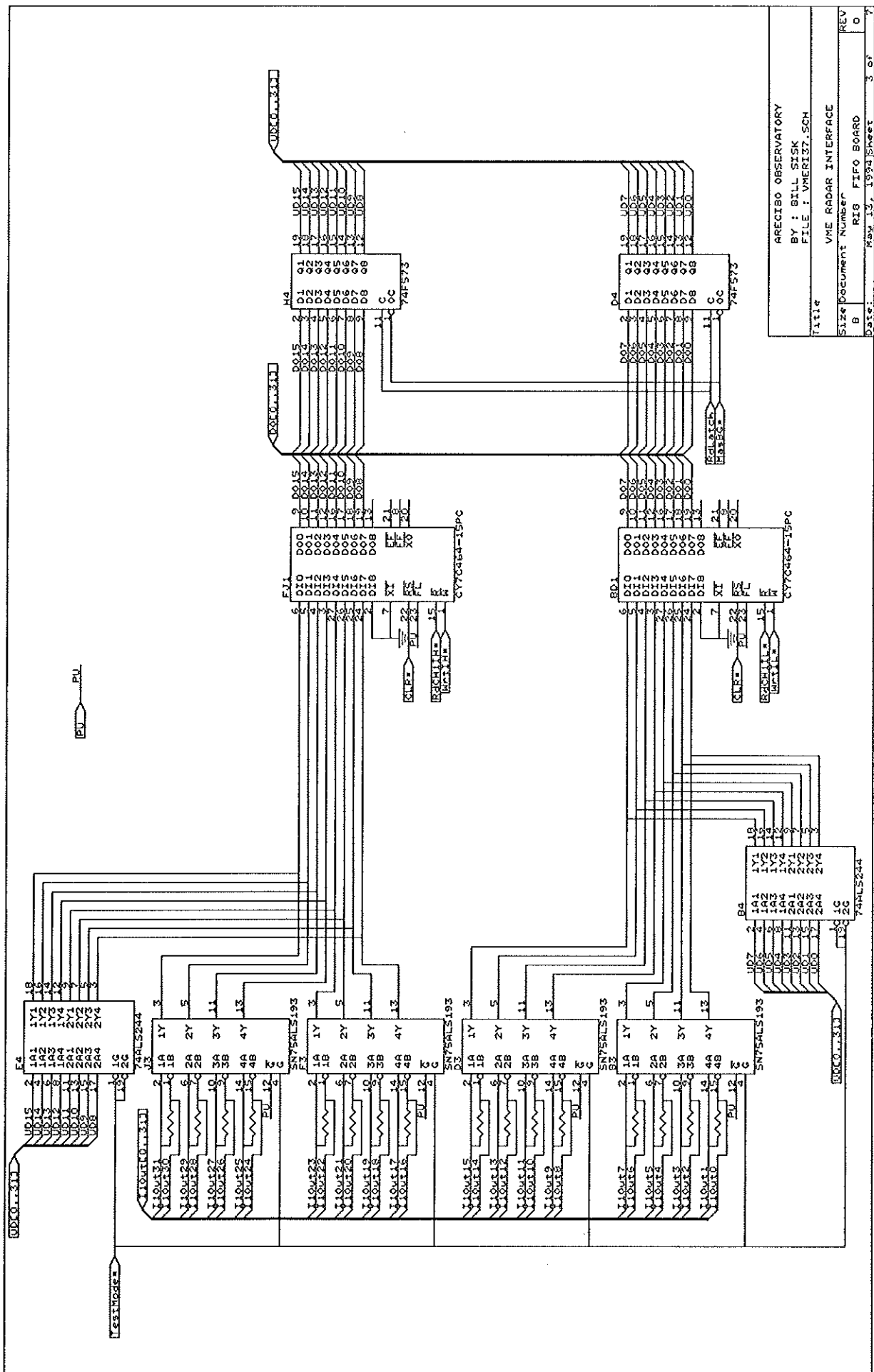
REV

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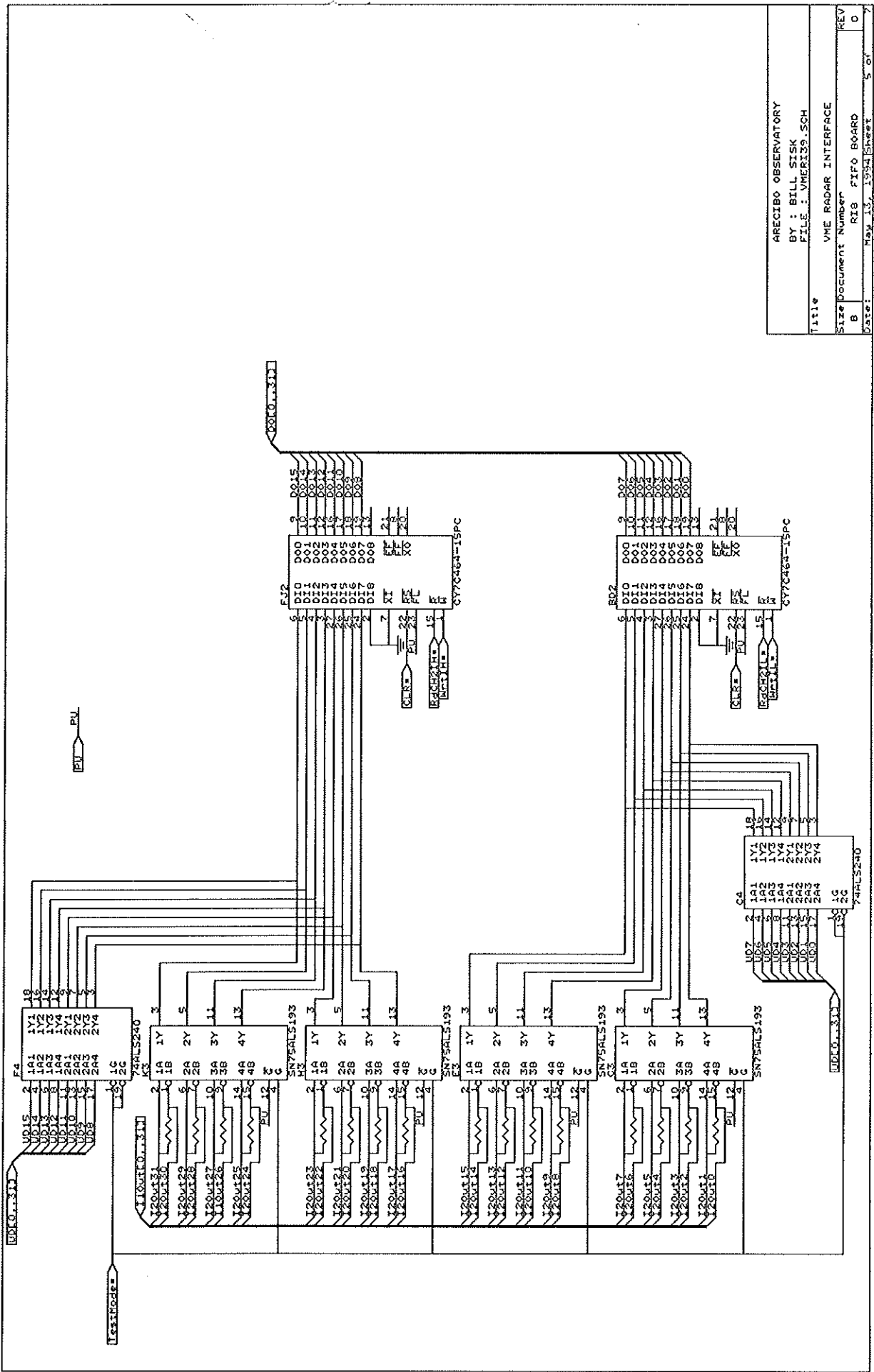
Date: January 4, 1992 Sheet

of

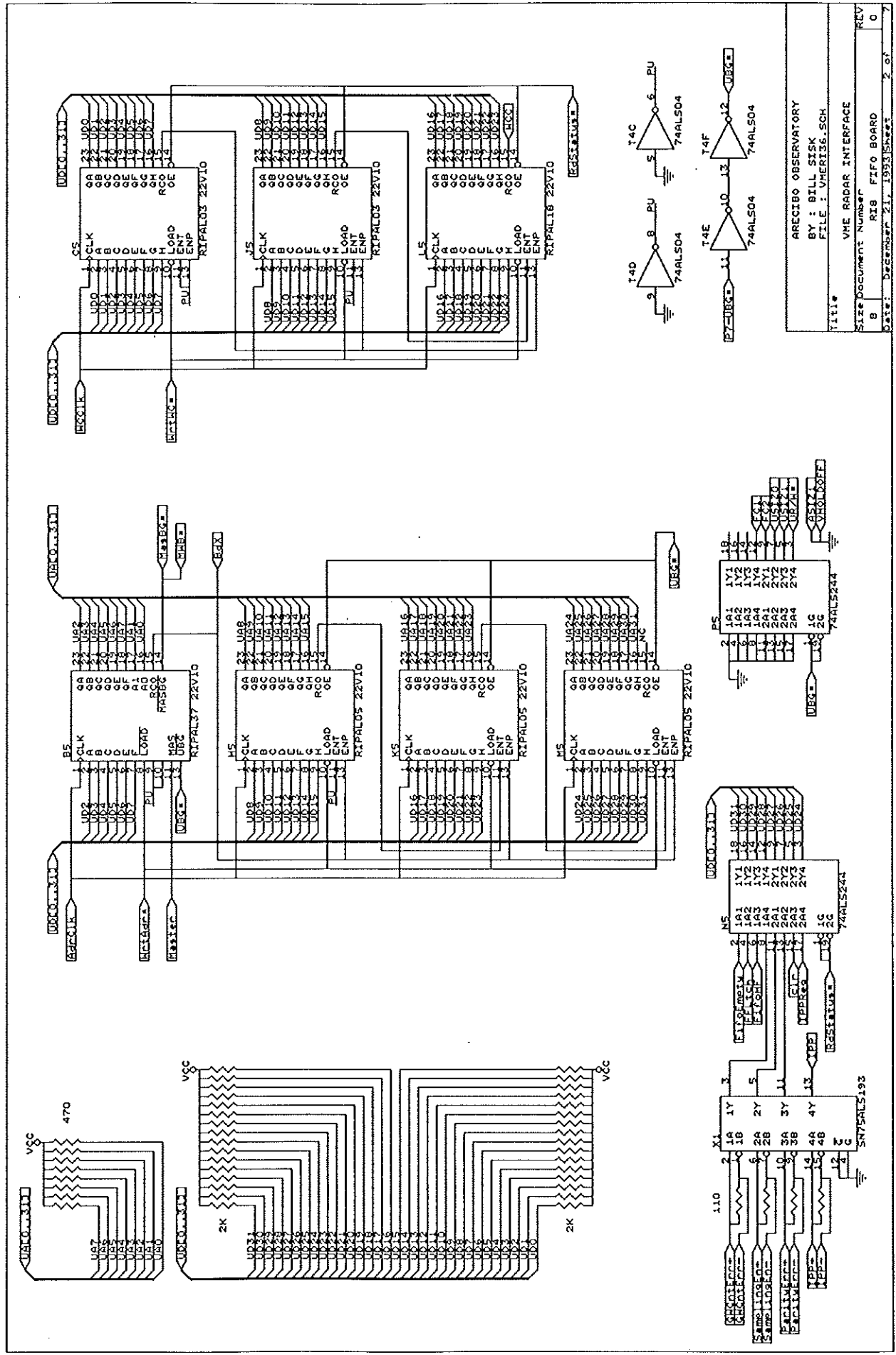




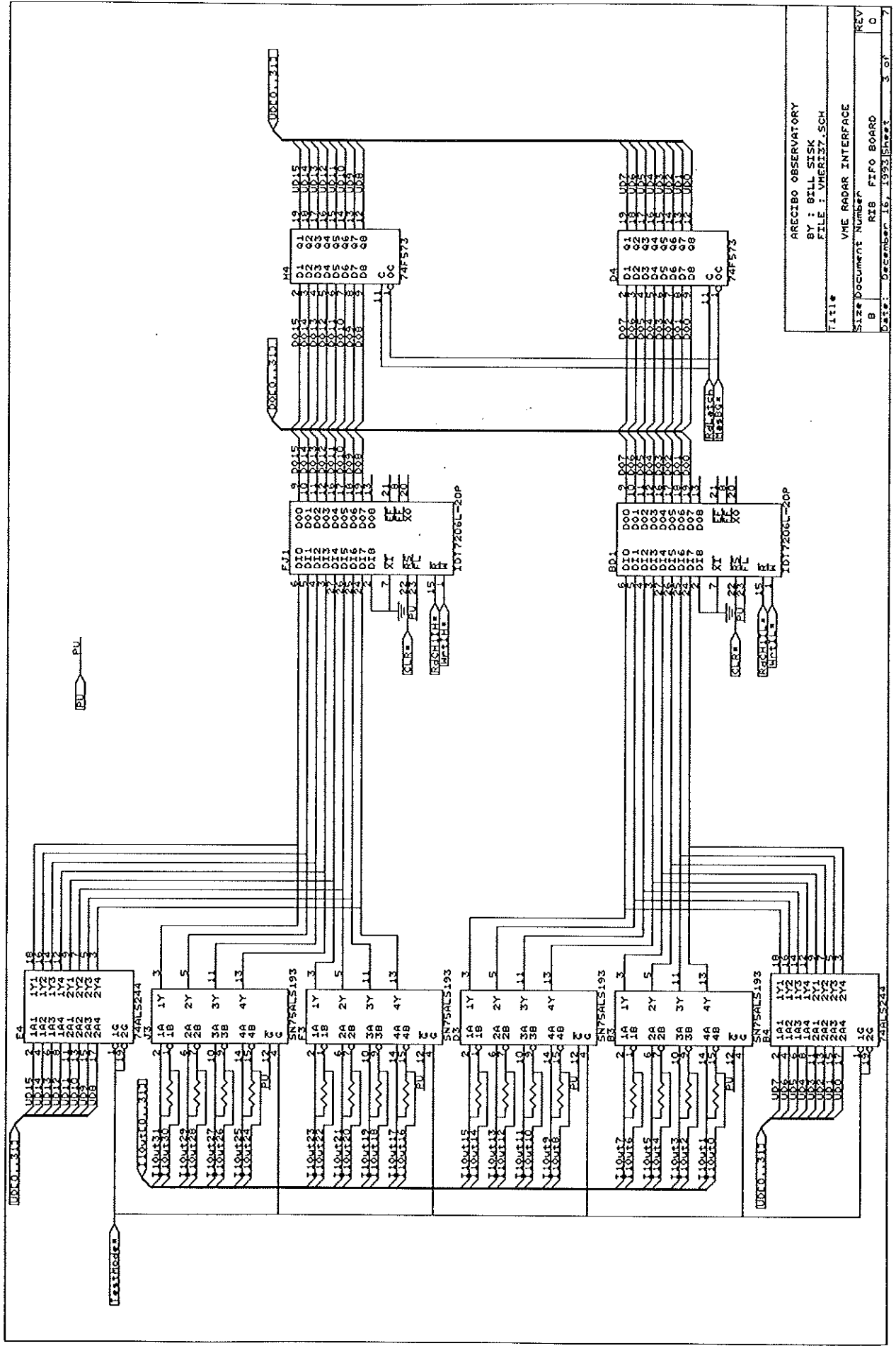
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 BY : BILL SISK
 FILE : VMER137.SCH
 Title
 Size Document Number
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 Date: May 13, 1994 16:02 3 of 7



ARECIBO OBSERVATORY
 BY : BILL SISK
 FILE : VMERT39.SCH
 Title
 Size Document Number
 8 R18 FIFO BOARD
 Date: May 13, 1994 Sheet 5 of 7



TITLE: VME RADAR INTERFACE
 BY: BILL SISK
 FILE: VMERIS6.SCH
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 REV: 0
 Date: December 21, 1993 Sheet 2 of 7

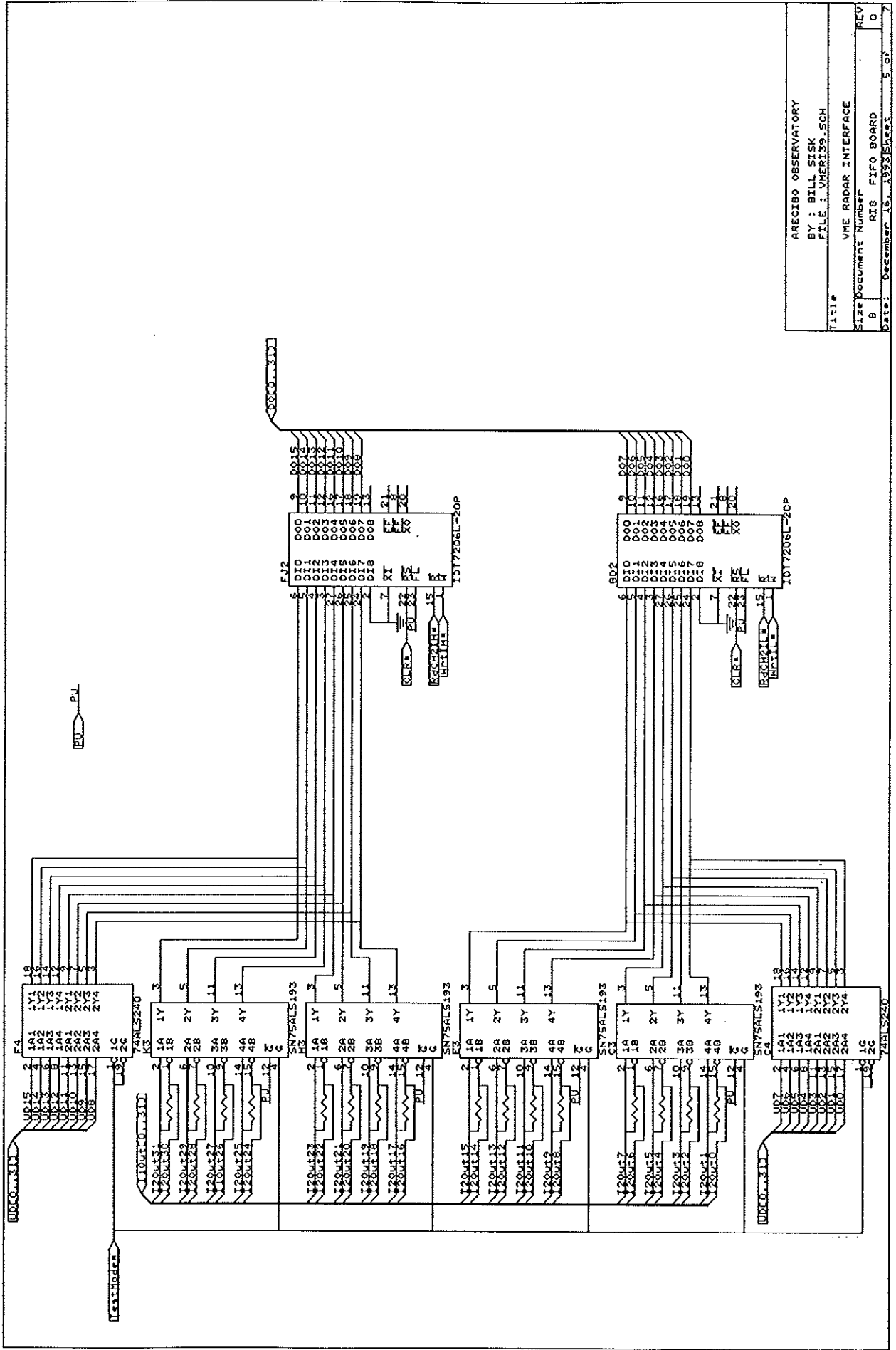


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Title
 VME RADAR INTERFACE

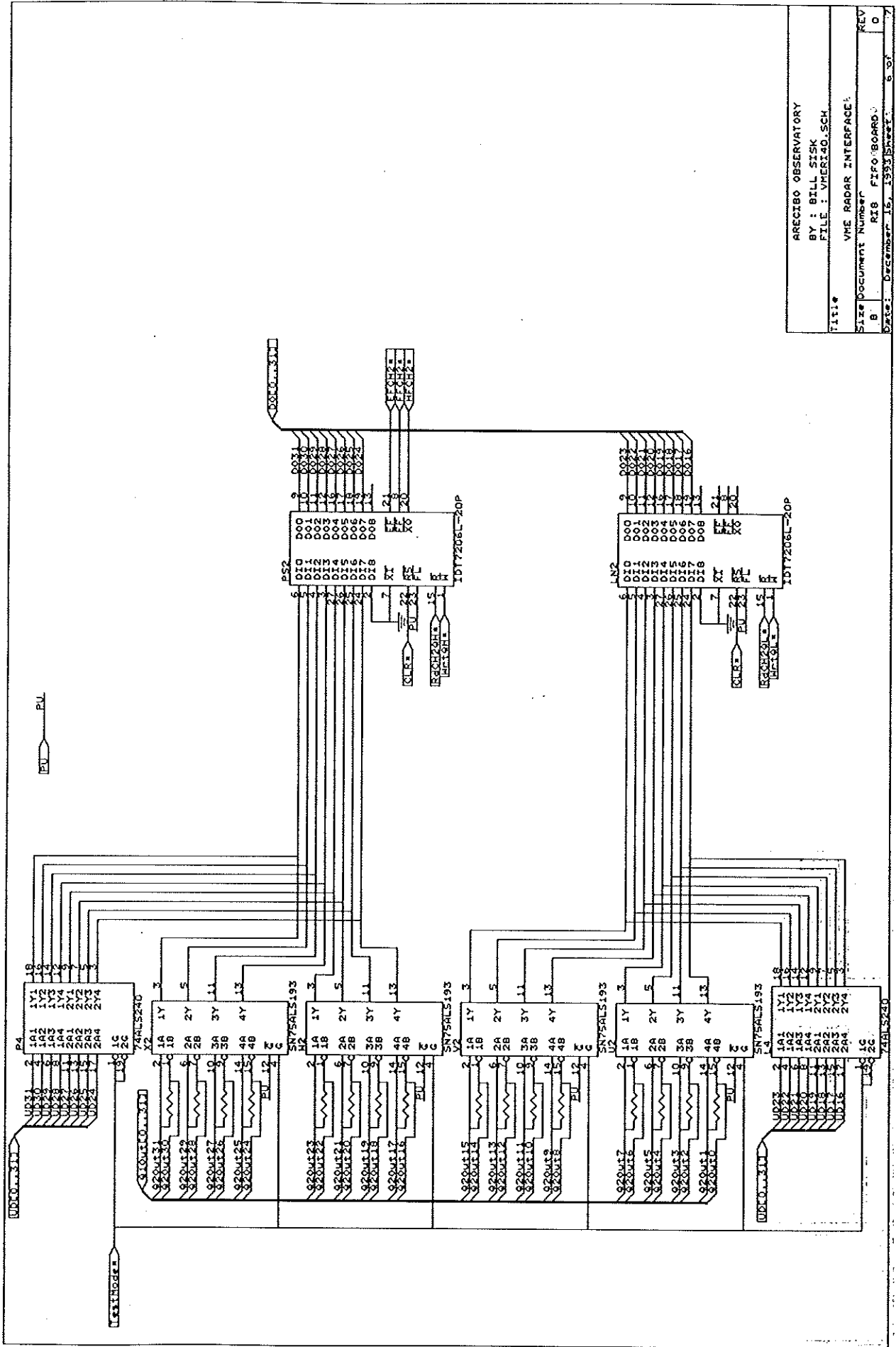
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 B RIB FIFO BOARD

Date: December 16, 1993 Sheet 3 of 7

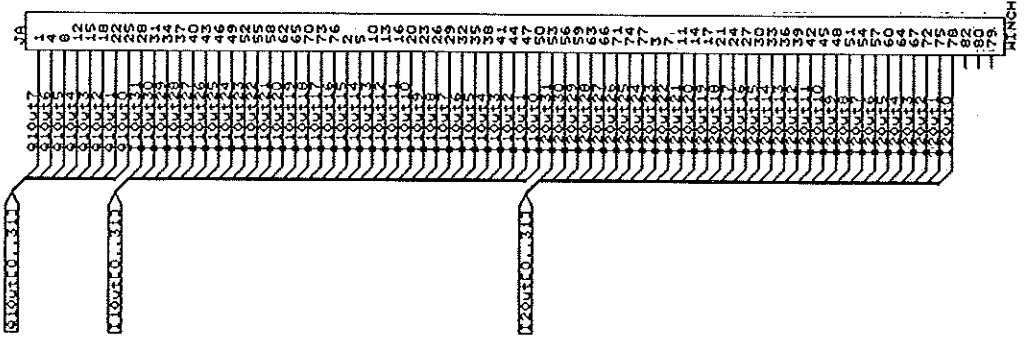
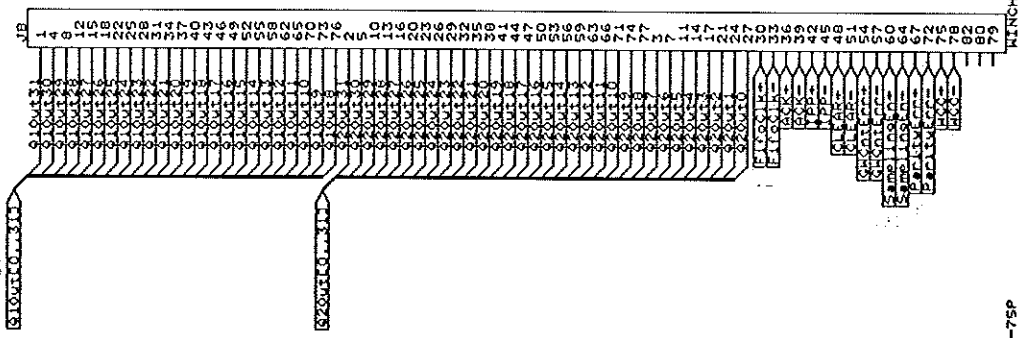
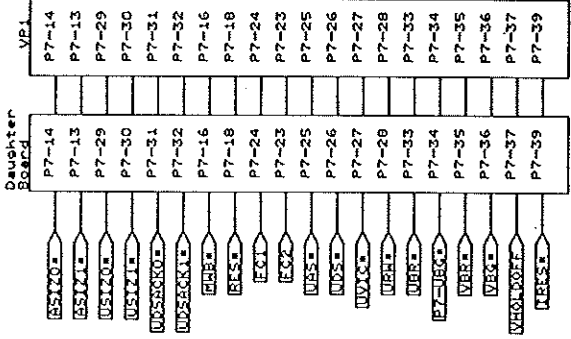
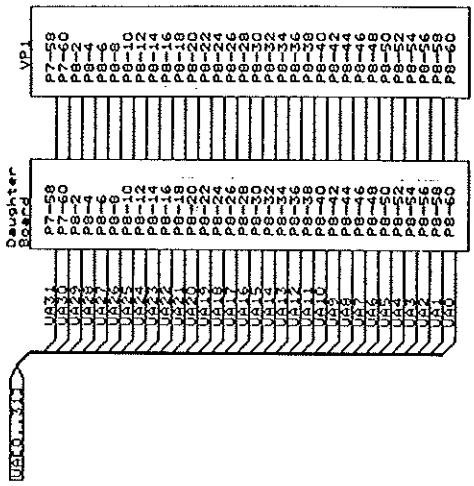
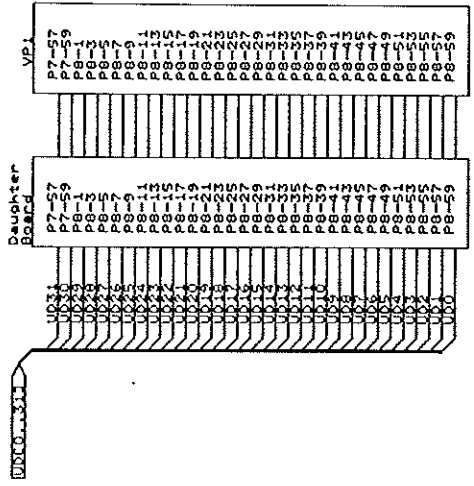


ARECIBO OBSERVATORY
 BY : BILL SISK
 FILE : VMERIS9.SCH

Title VME RADAR INTERFACE
 Size Document Number B R18 FIFO BOARD
 Date: December 16, 1993 Rev: 5 of 7



ARCCIBO OBSERVATORY
 BY : BILL SISK
 FILE : VMER190.SCH
 Title* VME RADAR INTERFACE*
 Size Document Number
 B. R18 FIFO BOARD
 Date: December 16, 1993 Drawn: 6.07



ARCIBO OBSERVATORY
 BY : BILL SISK
 FILE : VMERTG1.SCH
 Title : VME RADAR INTERFACE
 Size Document Number :
 B P15 FIFO BOARD - CONNECTOR DIAGRAM 0
 Date : December 16, 1993 Sheet 2 of 2

MINICH CON-75P

MINICH CON-75P